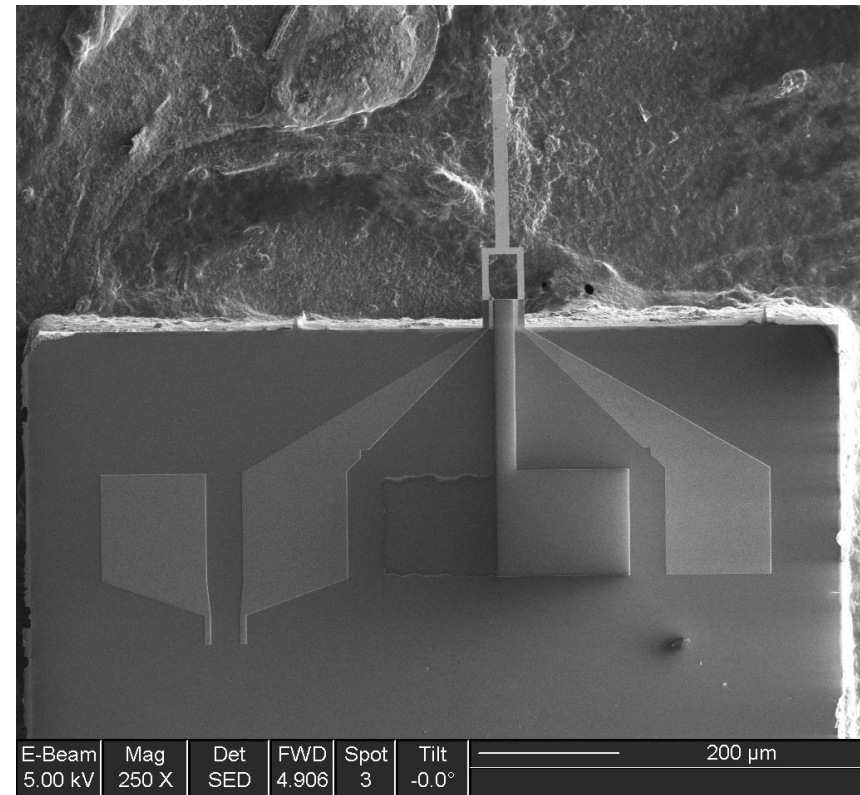


Research update: feedback control, device testing, and more

Joey Doll

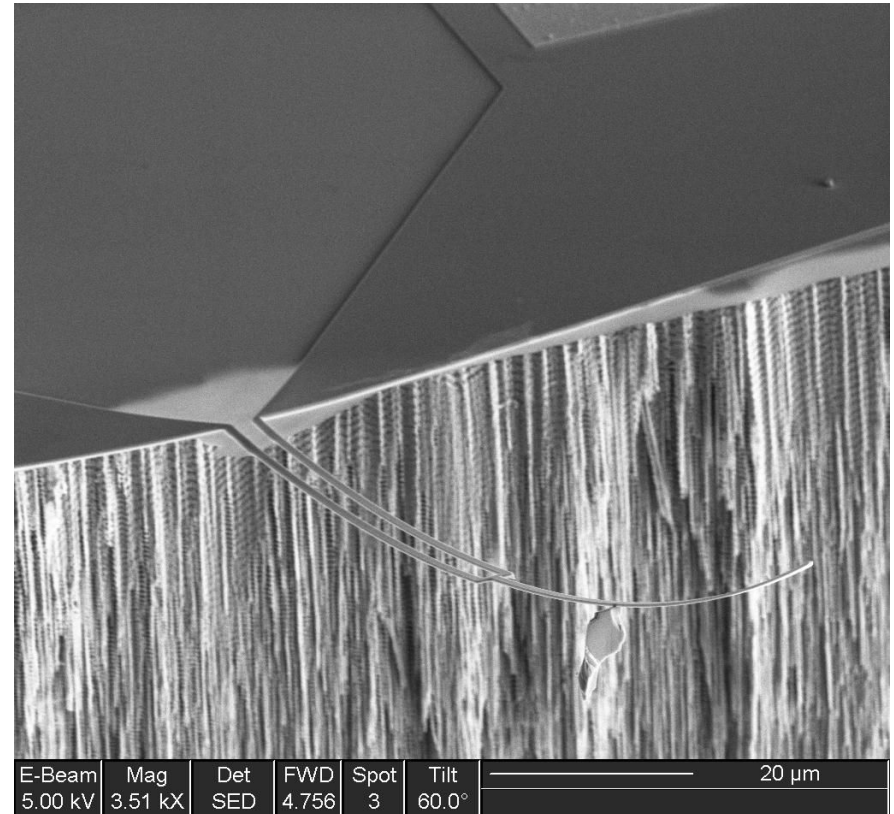
Group Meeting

11/4/2009

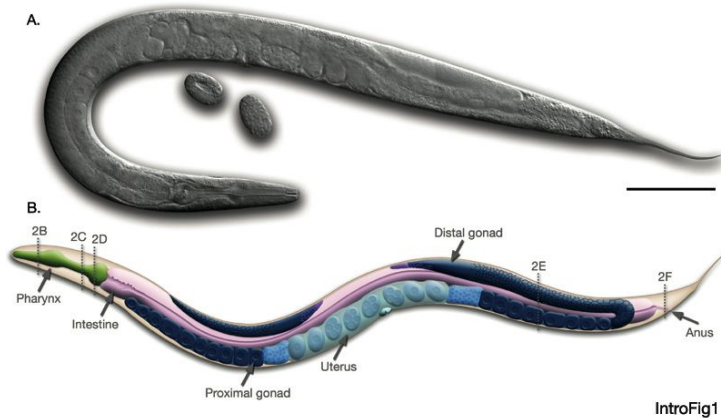


Today

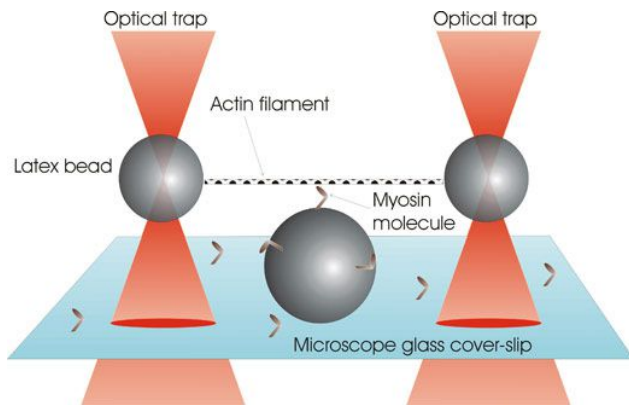
- Amplifier and feedback circuitry
- Combined PR+PE testing
- Cantilever bending stress



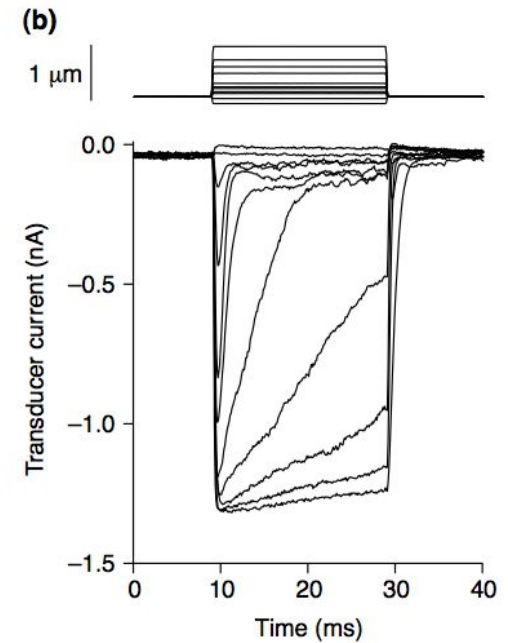
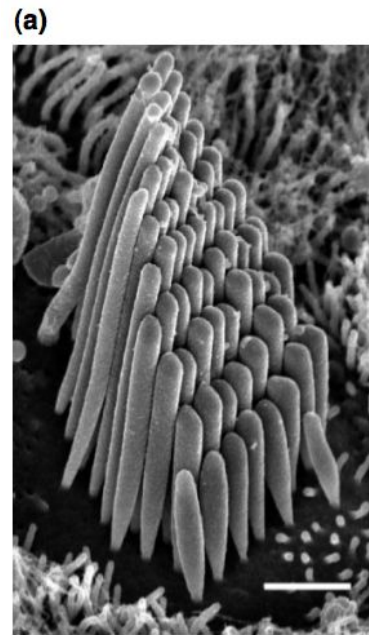
Motivation



Sense of touch (TRNs)



Protein conformational changes

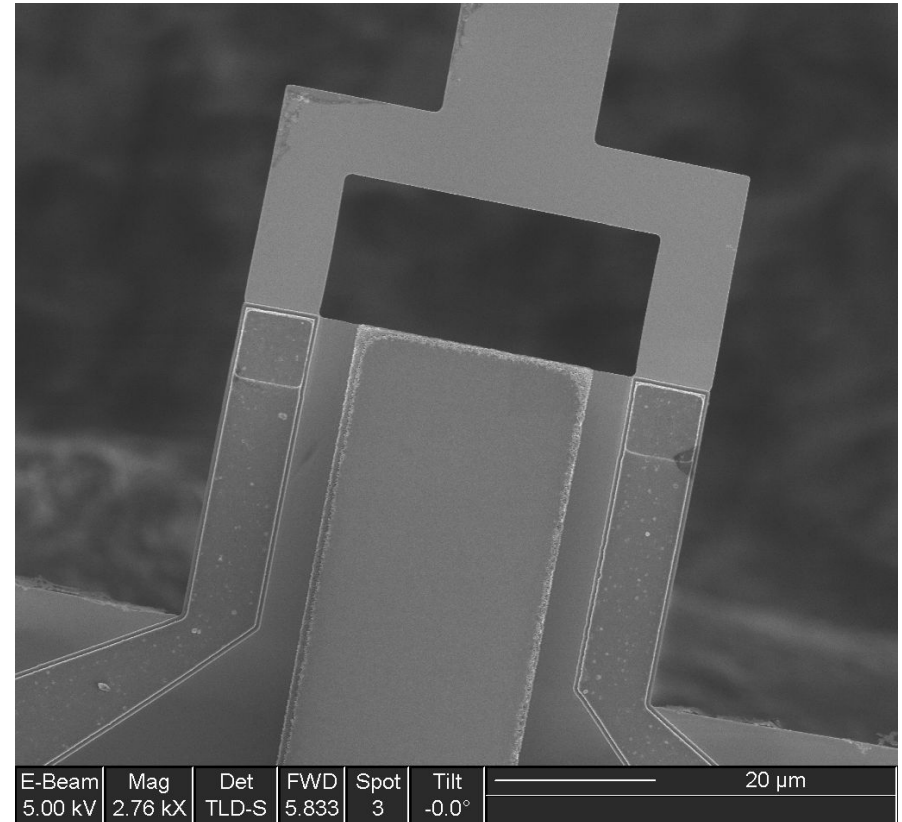
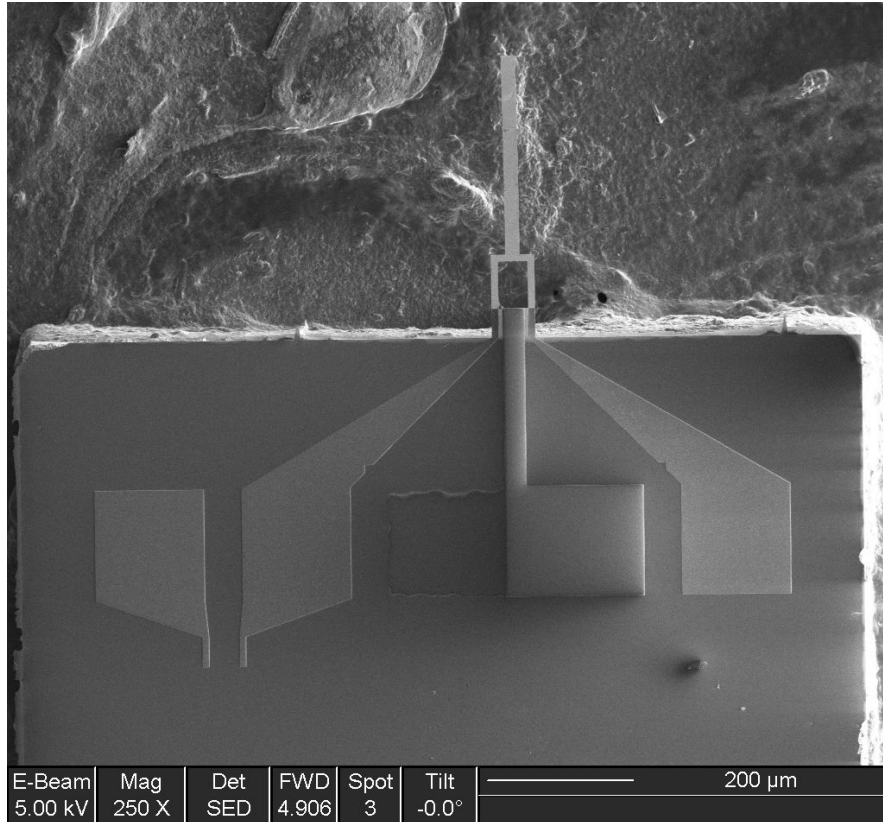


Sense of hearing (hair cells)

Performance Goals

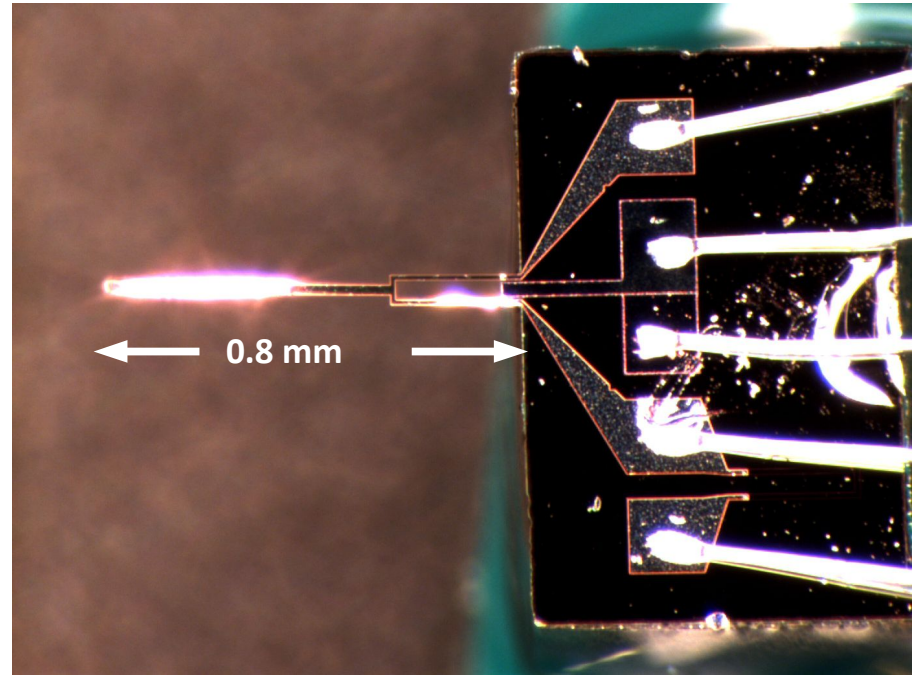
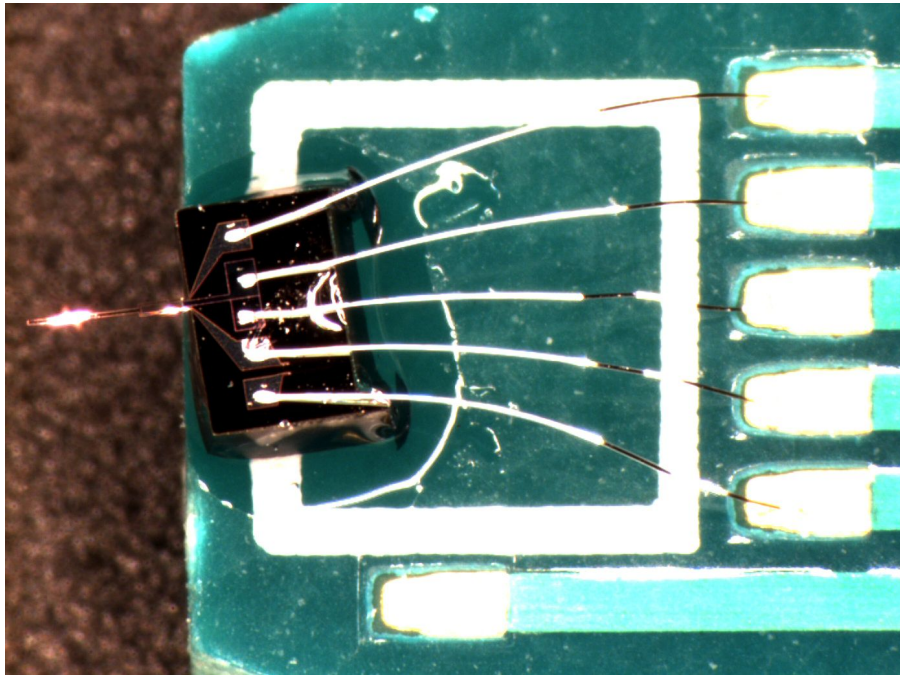
- Rise time
 - 10 microseconds (turtle hair cell)
 - 1 microsecond (mammalian hair cell)
- Force resolution
 - 50 pN, 1 Hz – 30 kHz (turtle)
 - 50 pN, 1 Hz – 300 kHz (mammalian)
 - 30 pN, 1 Hz – 10 kHz (TRN, single molecule)
- Closed loop force control
- Operation in fluid

The Device

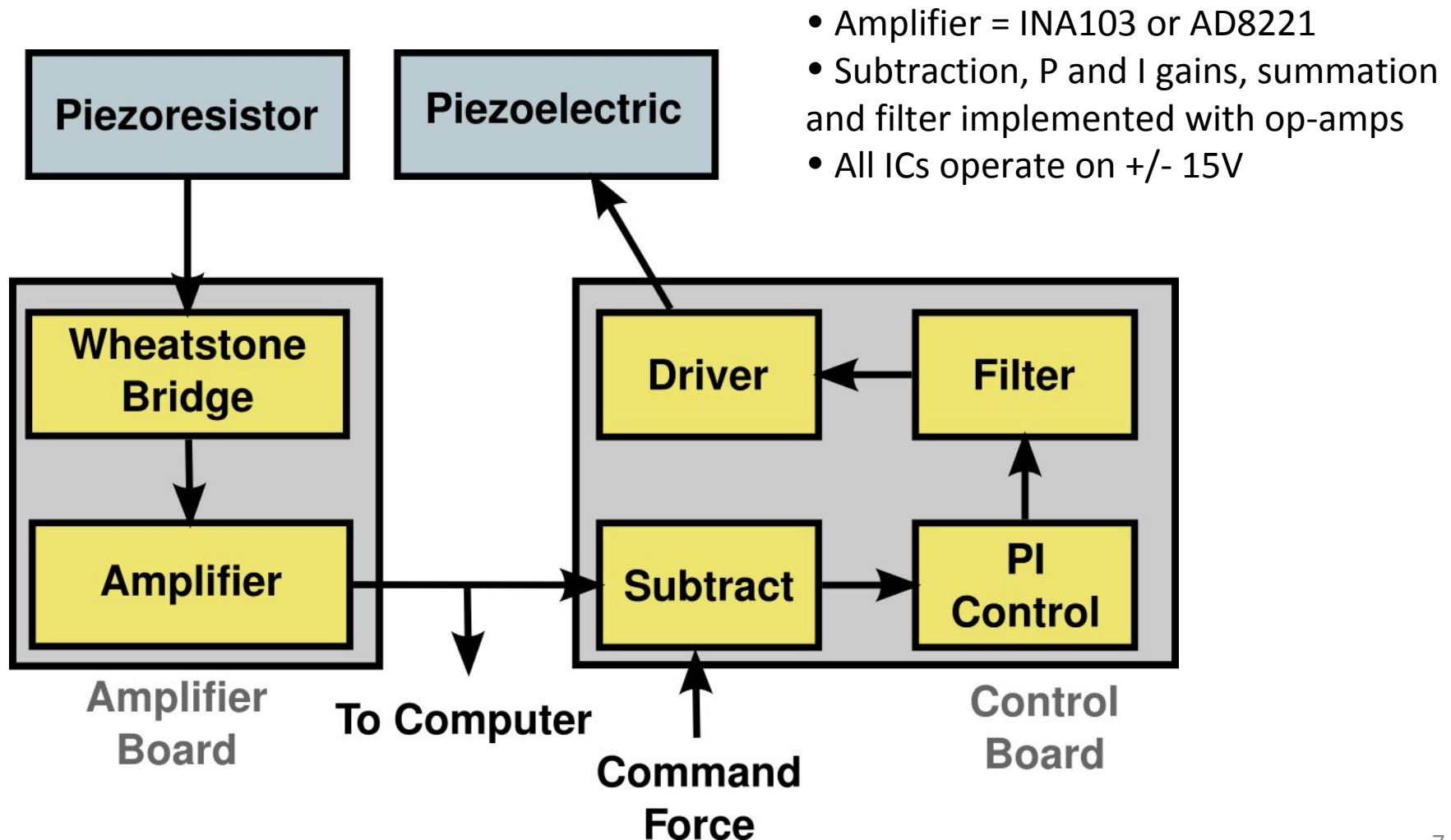


Piezoresistive force detection
Piezoelectric actuation

The Device

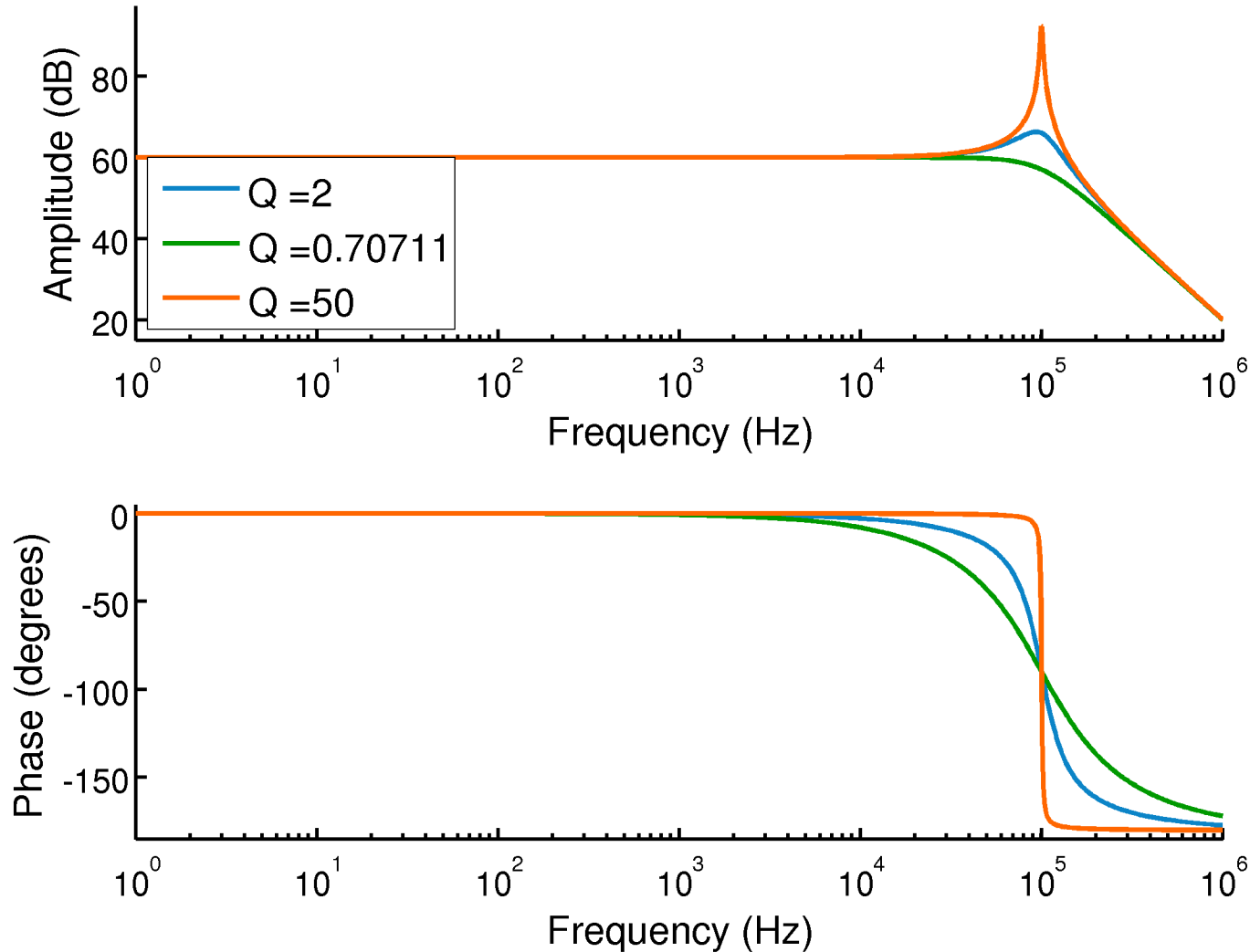


Feedback Circuit



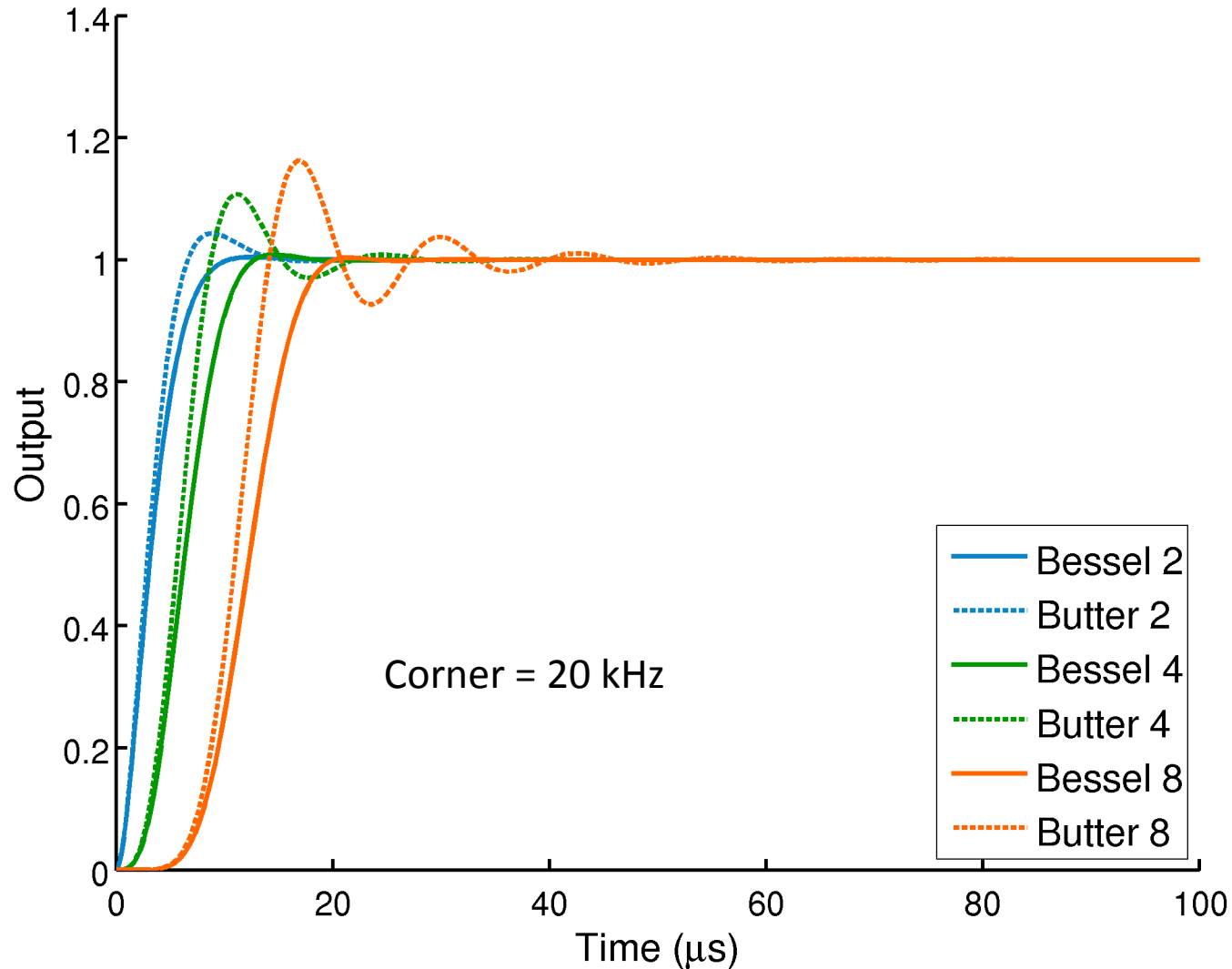
Feedback Modeling

Uncompensated cantilever open loop response



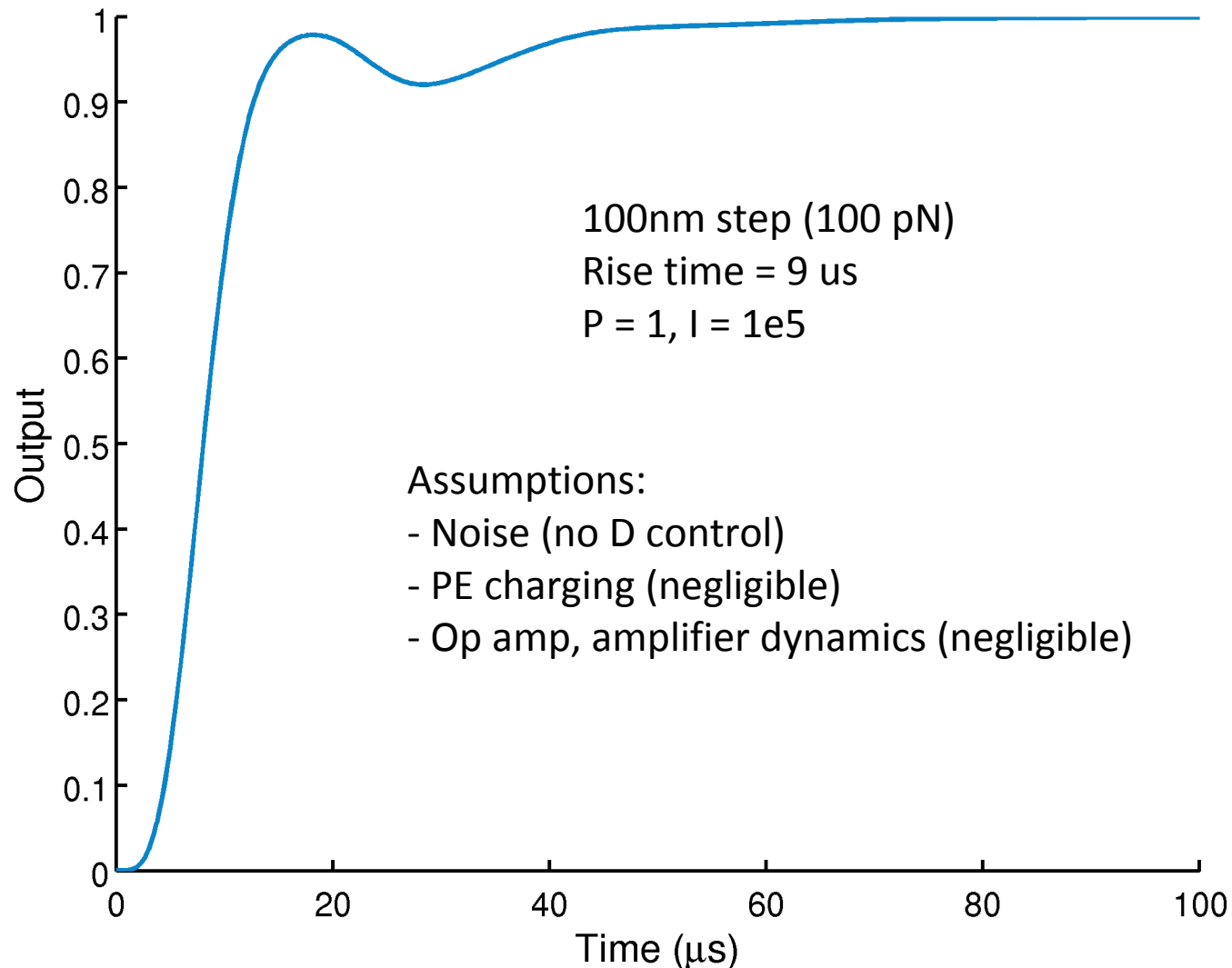
Feedback Modeling

Step response of bessel and butterworth filters

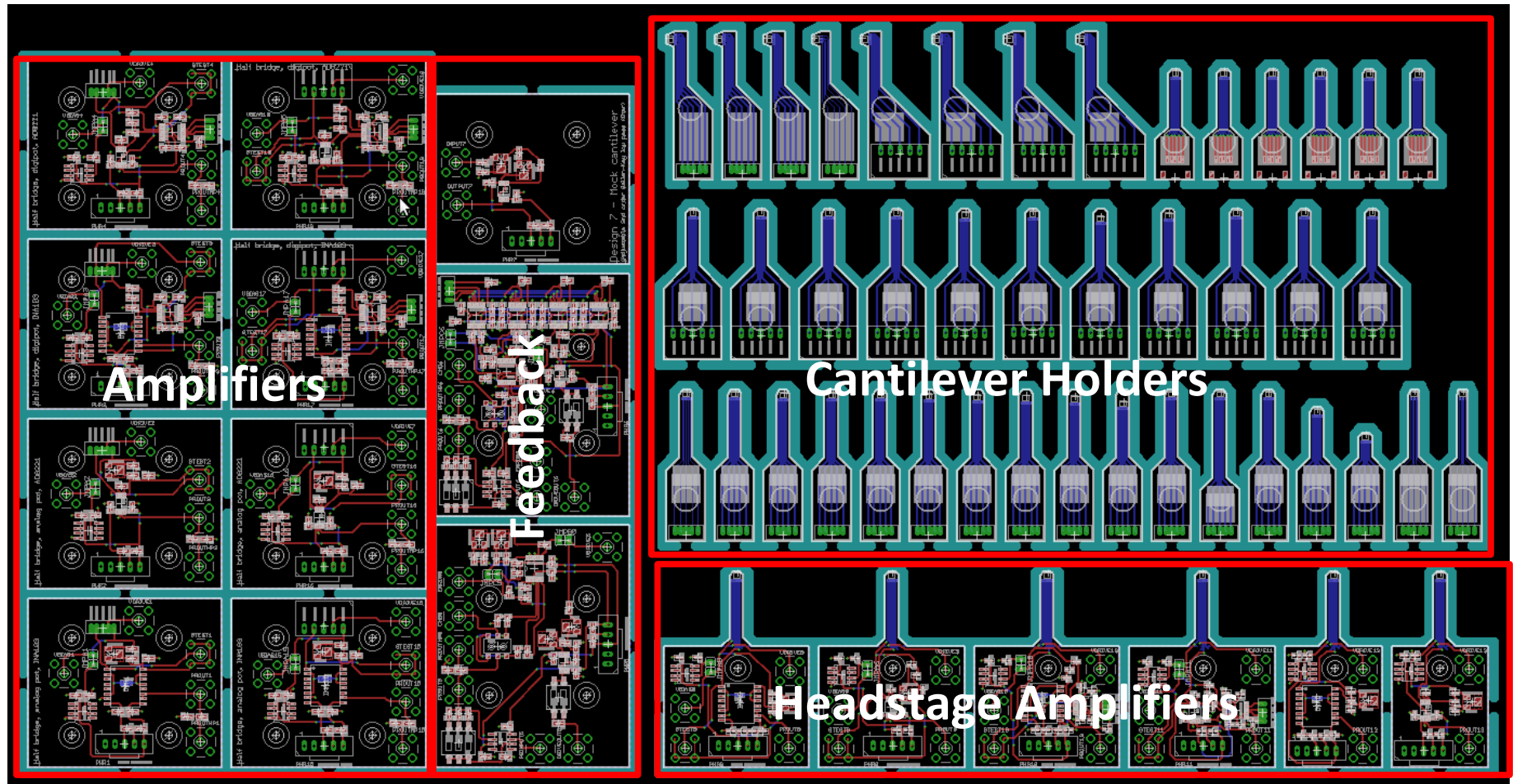


Feedback Modeling

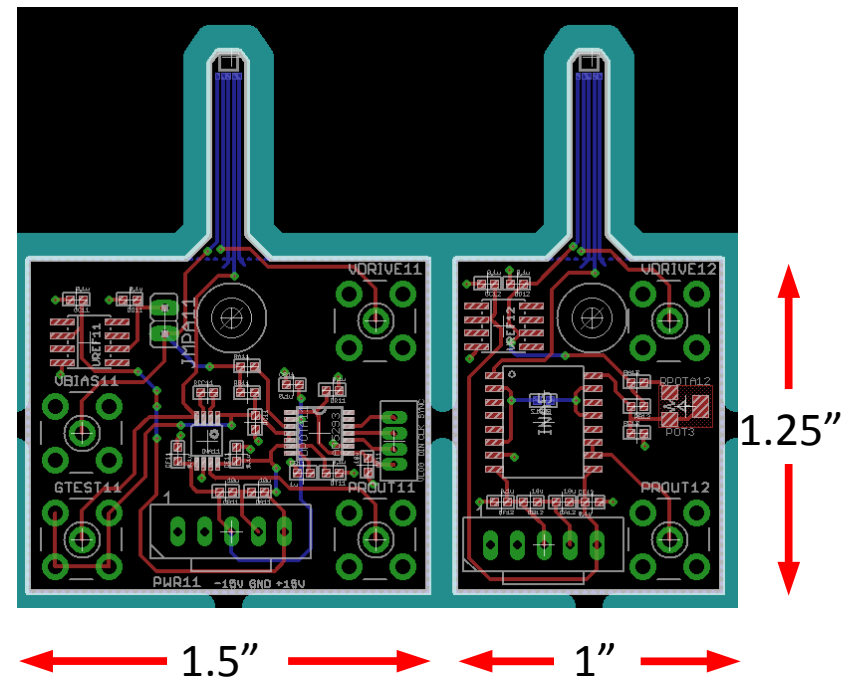
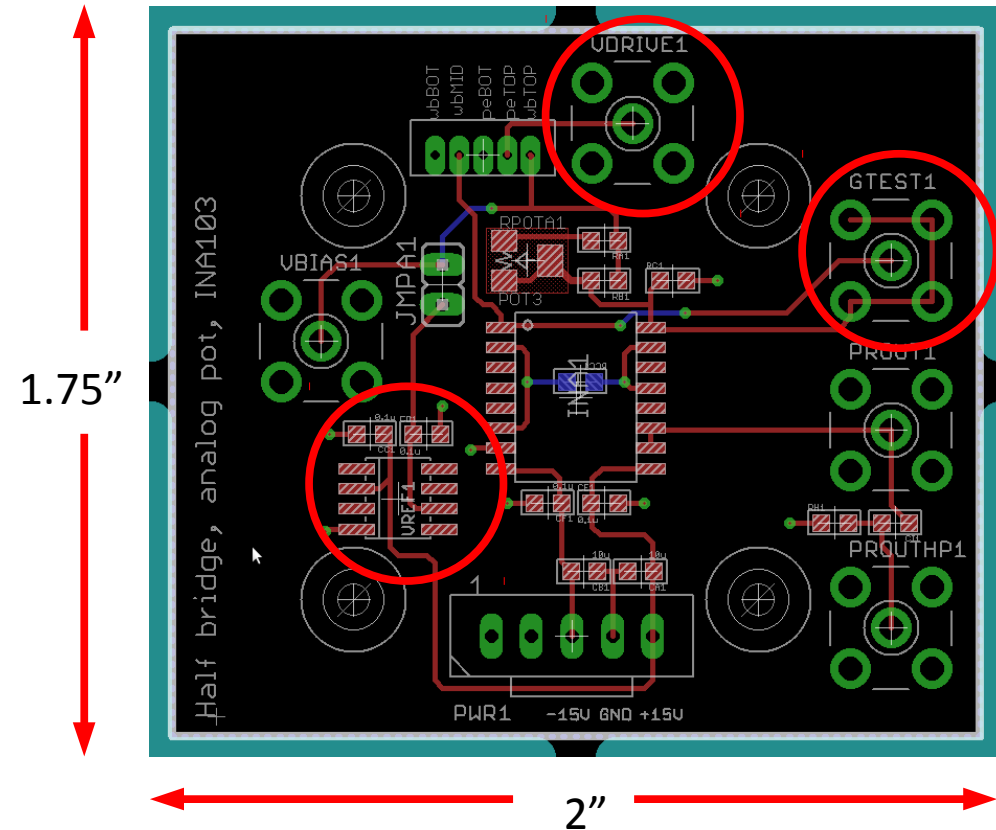
Closed loop, PID compensated, 2nd order Bessel, medium Q, lever = 100kHz, LP = 30kHz



PCB Layout

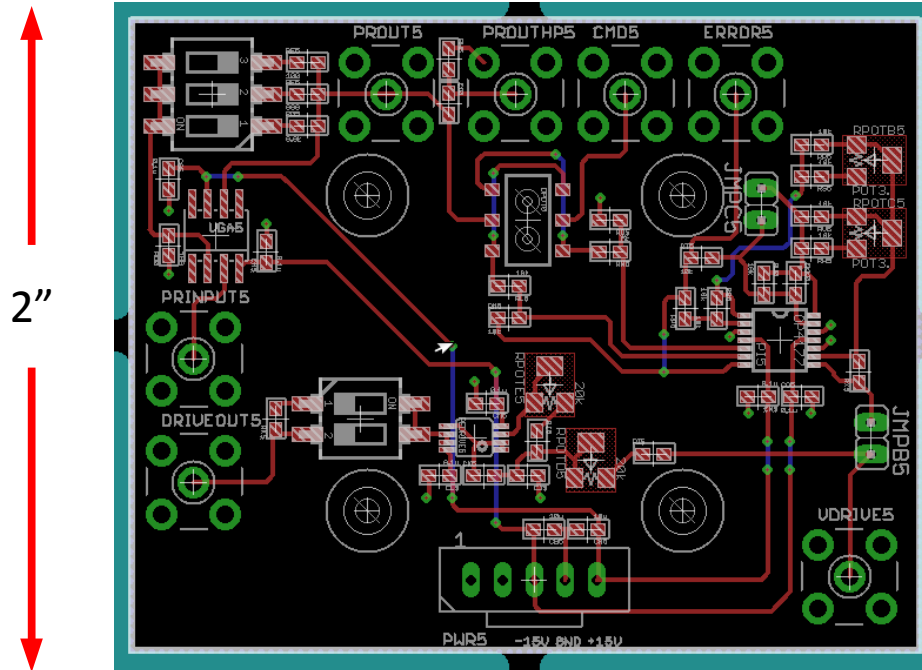


Circuits - Amplifiers

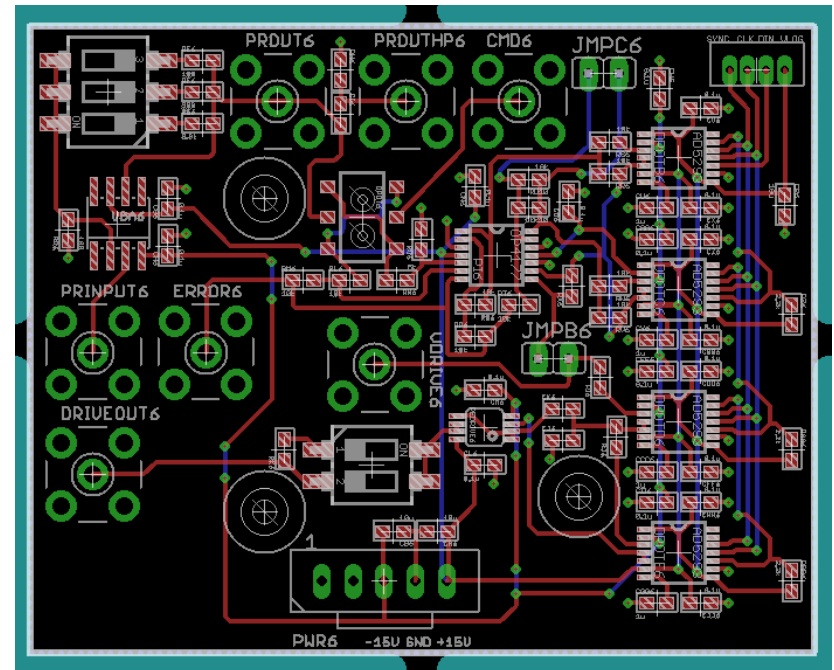


Circuits - Feedback

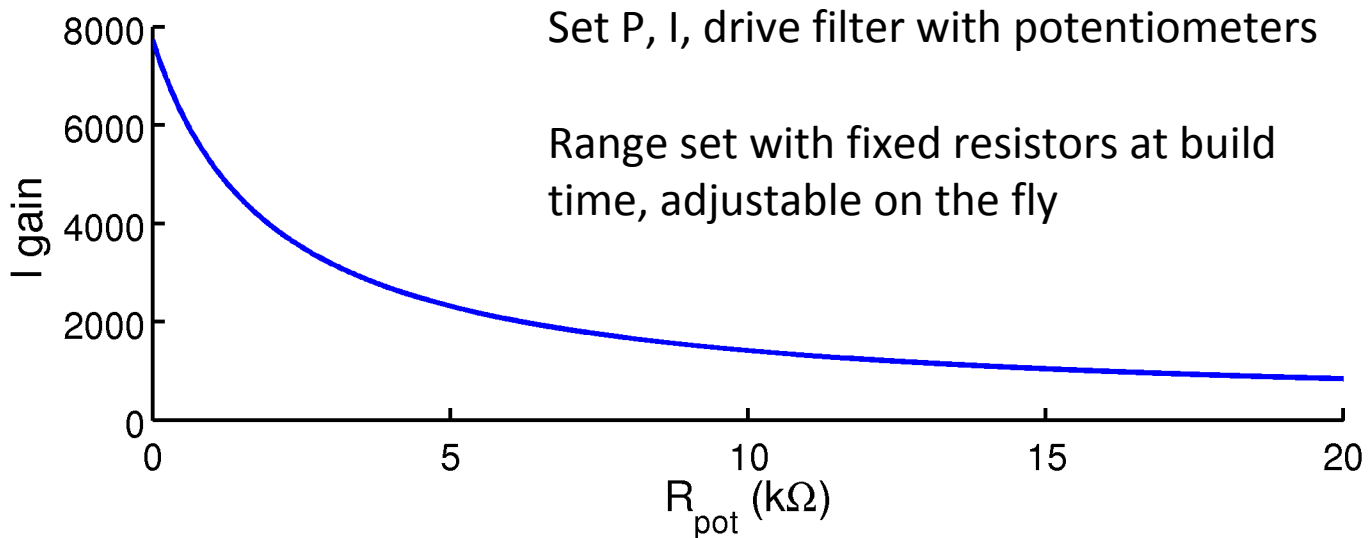
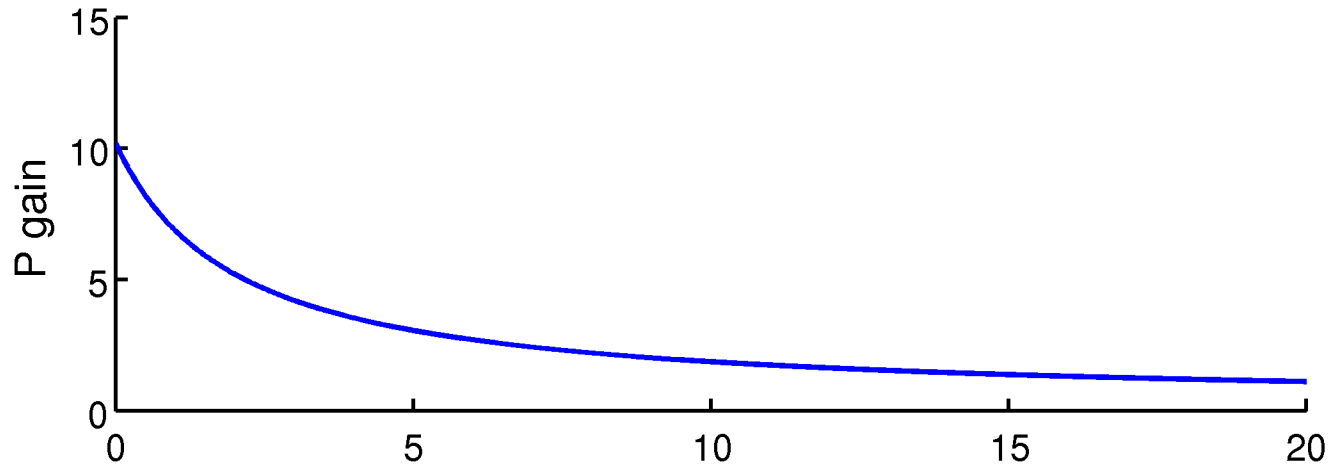
Analog Potentiometers



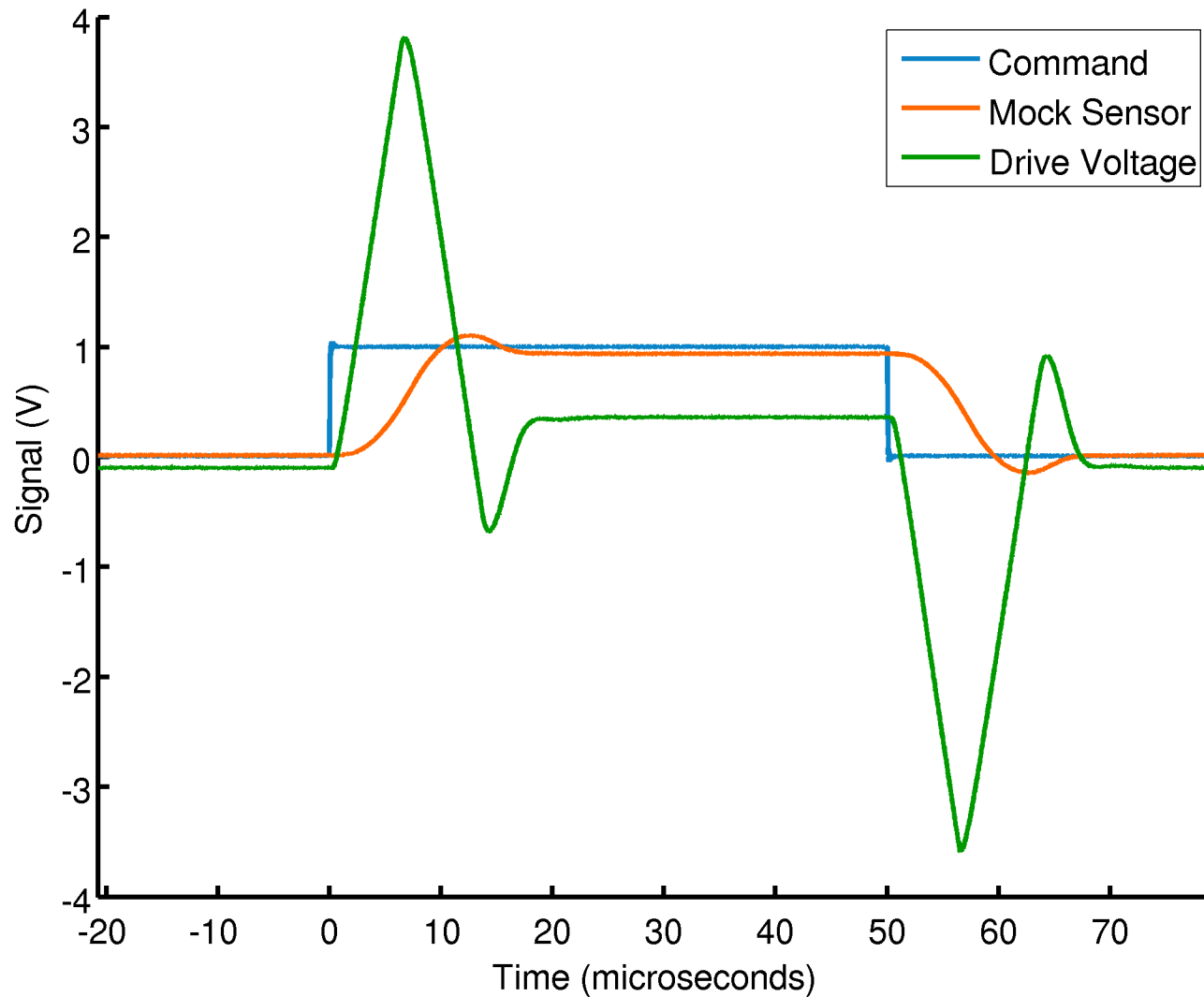
Digital Potentiometers



Circuit Design



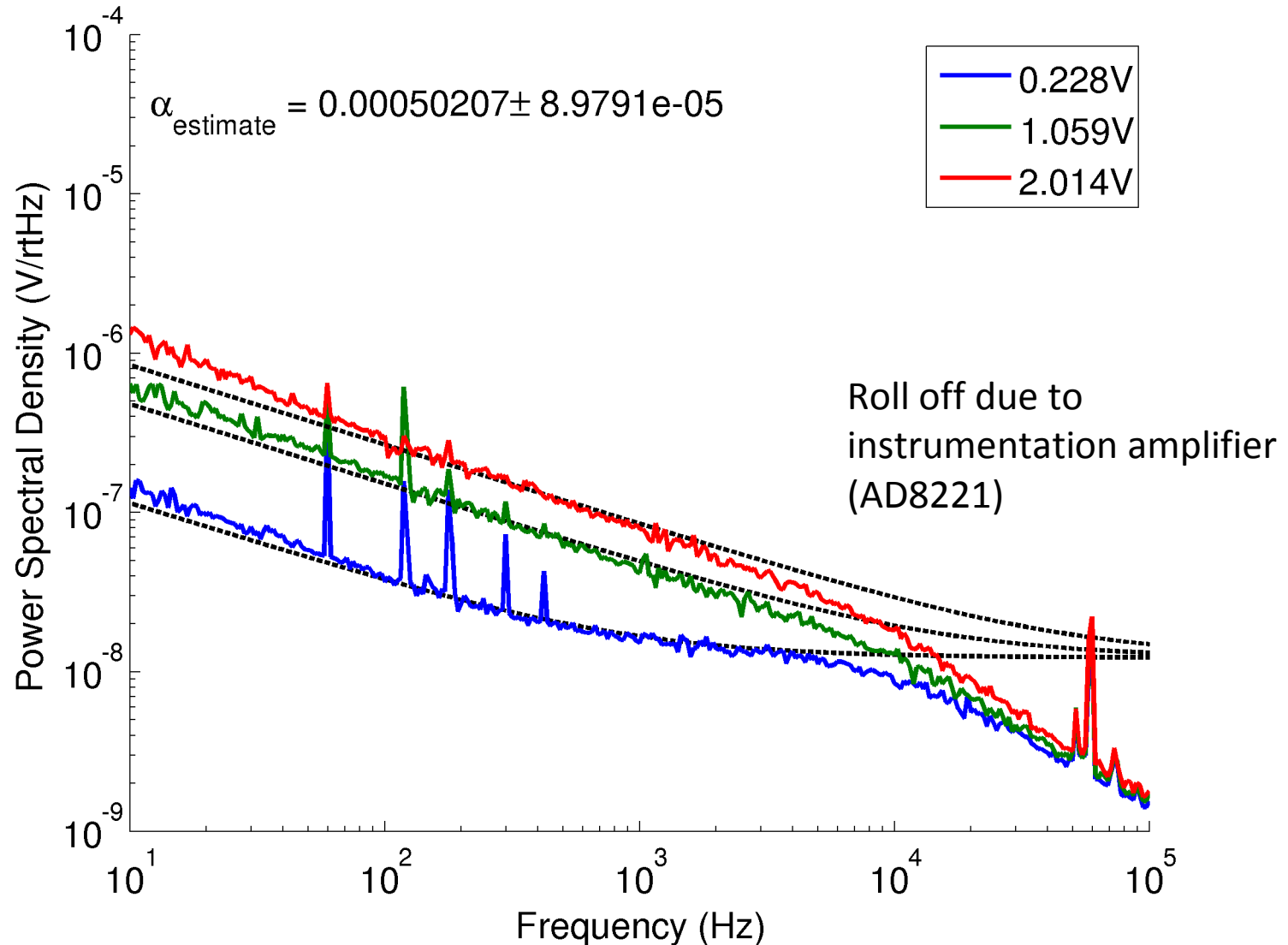
The circuit works



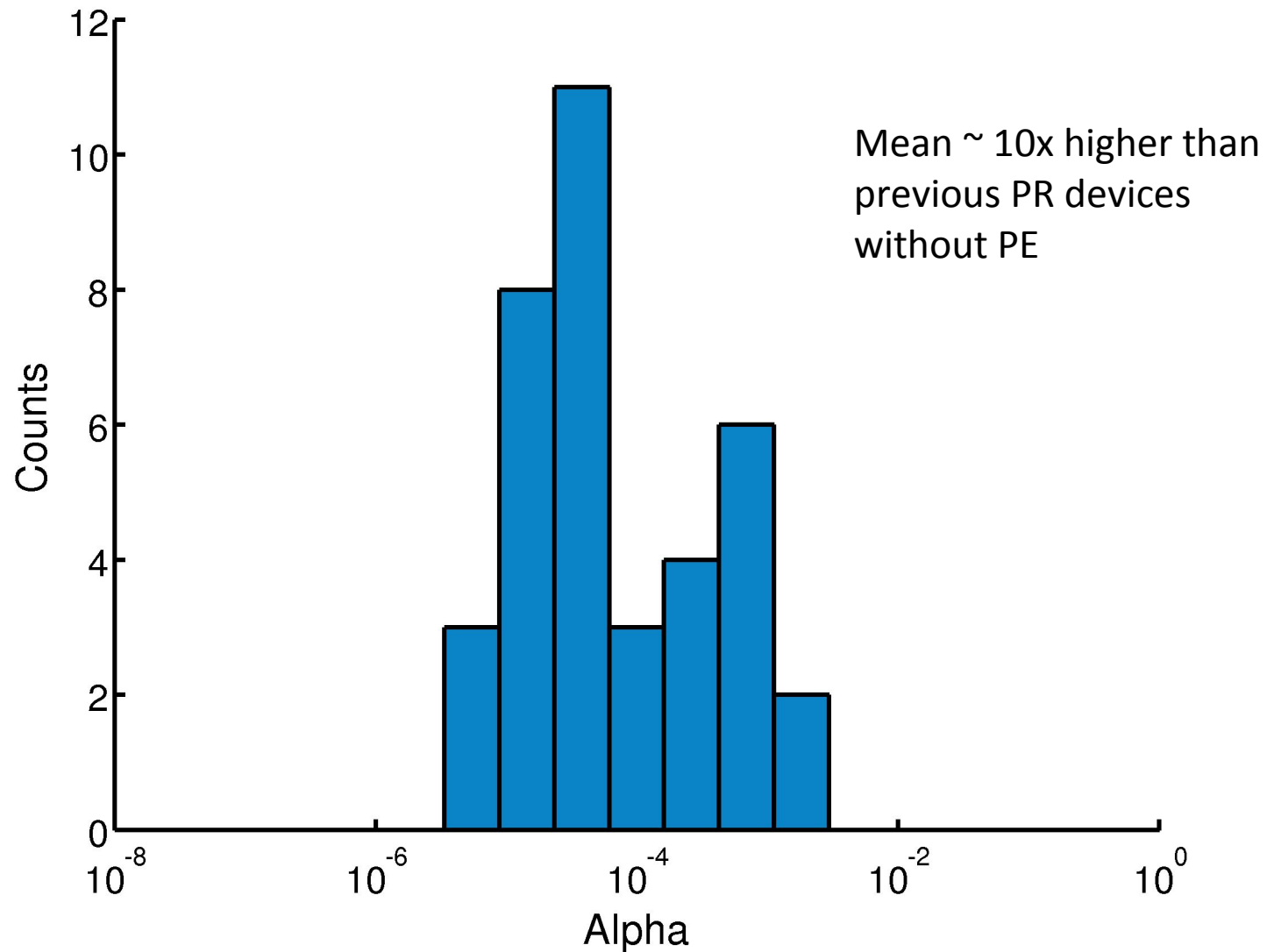
PR+PE Device Characterization

- **Noise spectrum**
- **Piezoresistor resistance**
- **Electrical cross-talk**
- Spring constant
- Force/displacement sensitivity
- Actuation distance

Noise spectra look good



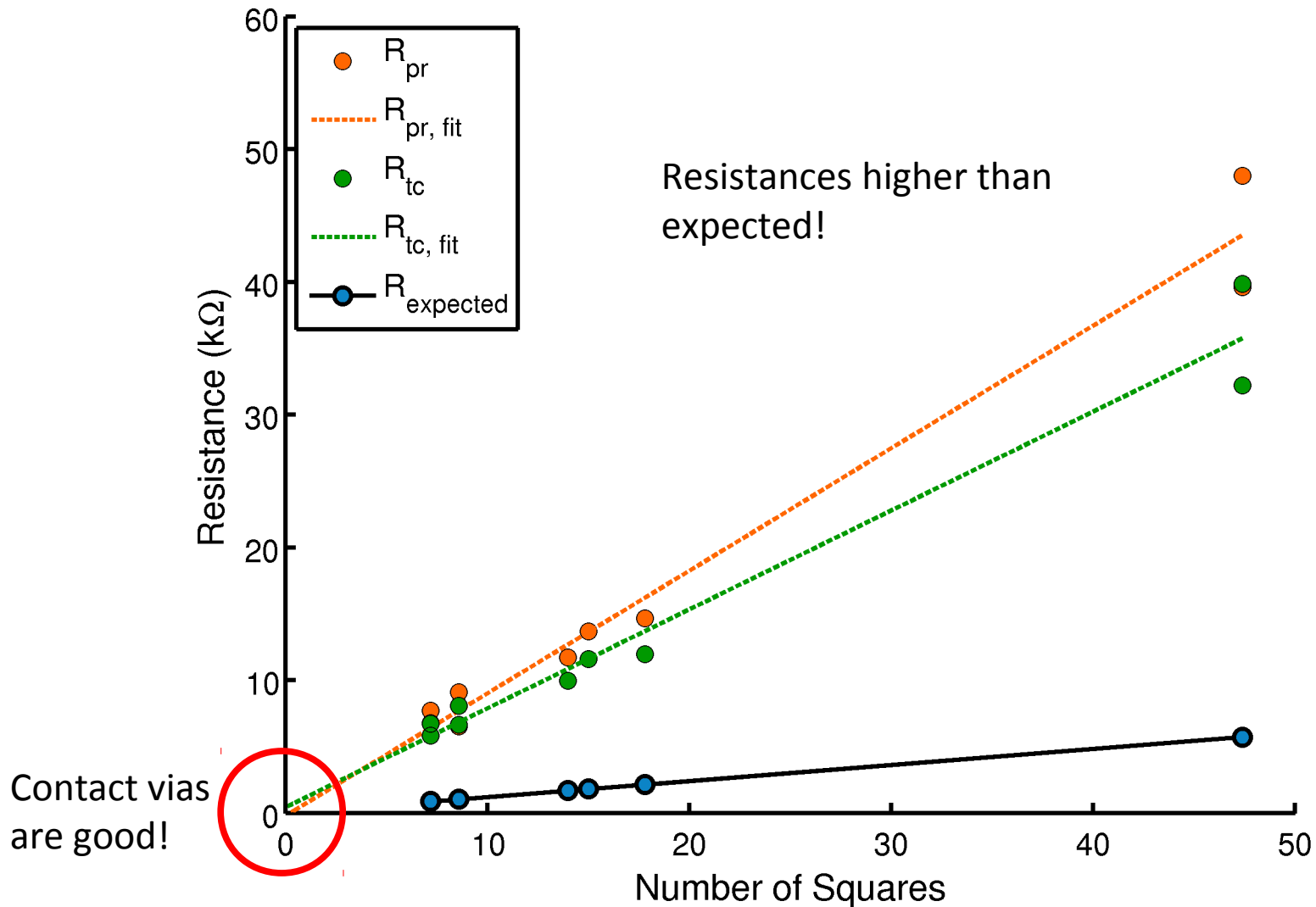
1/f noise higher than expected



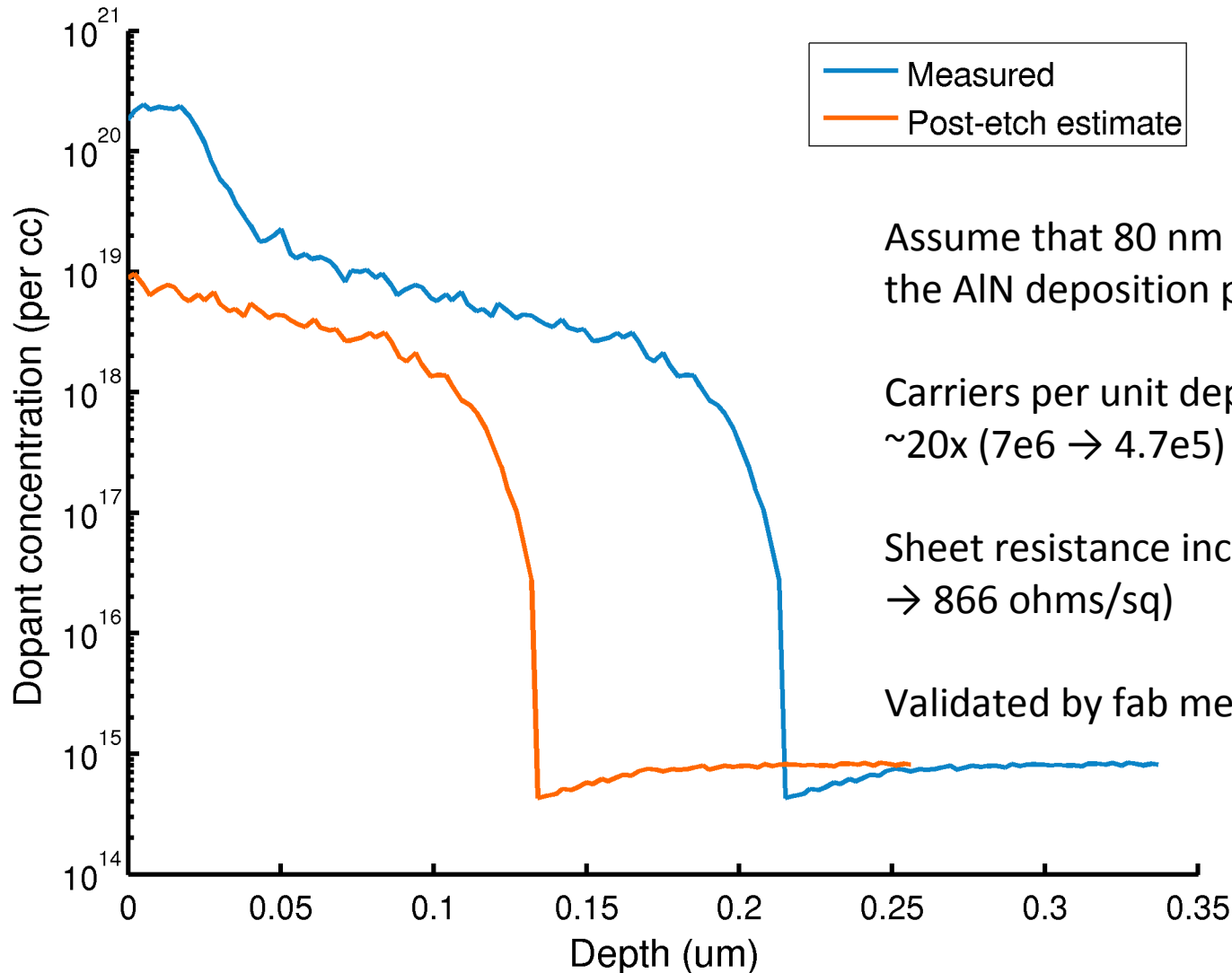
Two unknowns, one equation

- $1/f$ noise depends on α and the number of carriers
- α could be higher or the number of carriers could be smaller
- Need an additional parameter for fitting

Piezoresistor resistance



Accidental etching



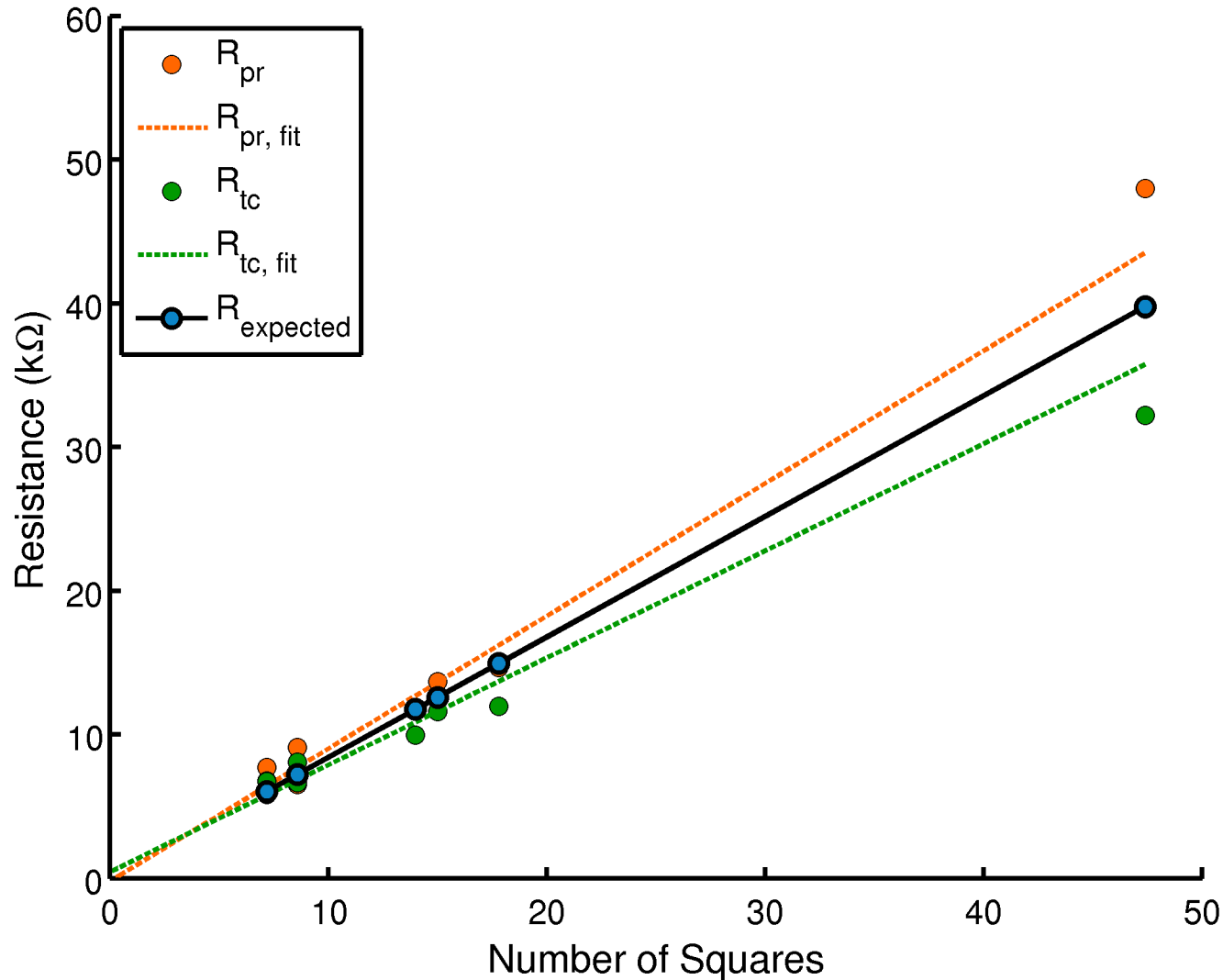
Assume that 80 nm of Si was etched in the AlN deposition preclean.

Carriers per unit depth decreases by ~20x ($7e6 \rightarrow 4.7e5$)

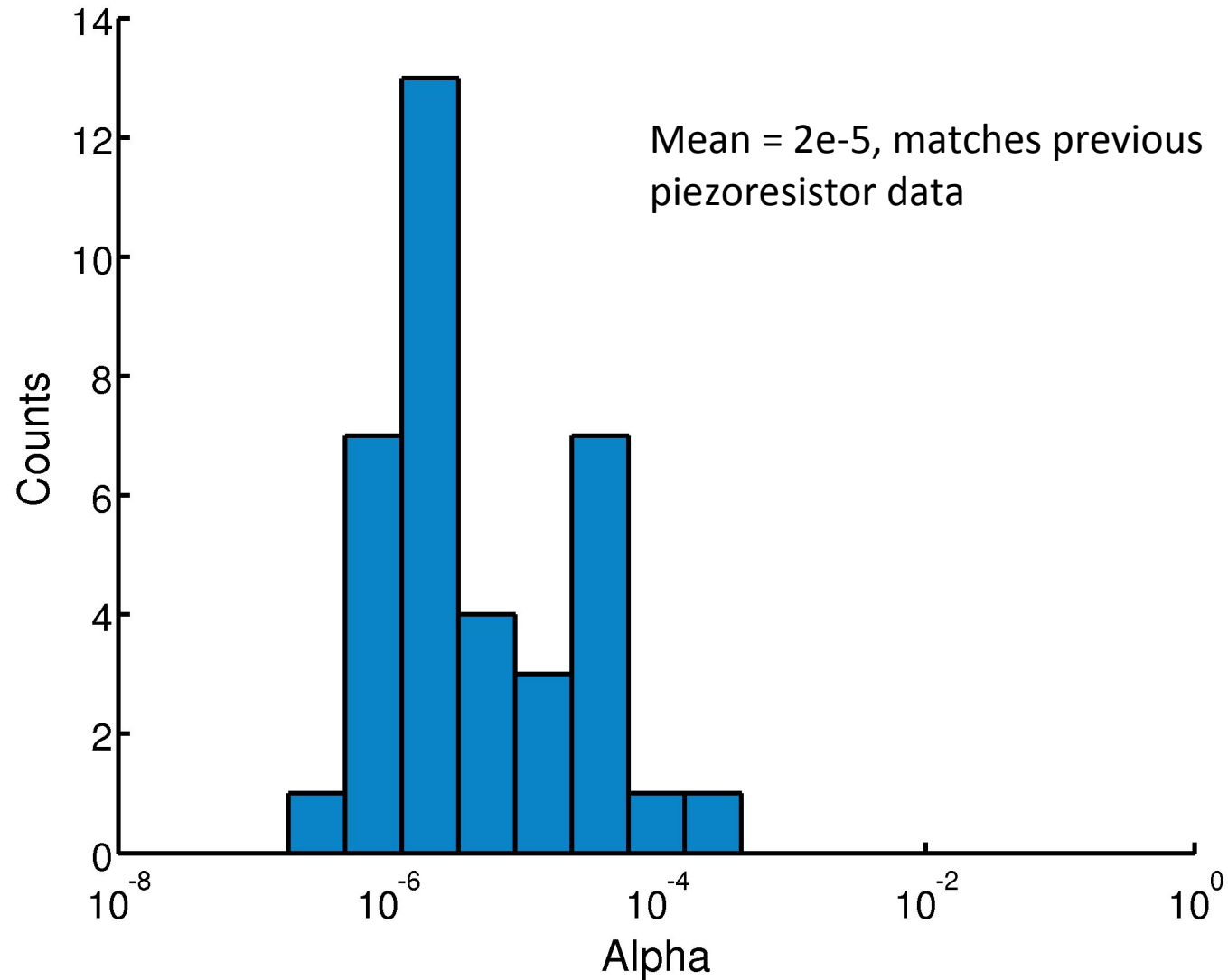
Sheet resistance increases by ~7x ($120 \rightarrow 866$ ohms/sq)

Validated by fab measurements

Adjusted resistance model



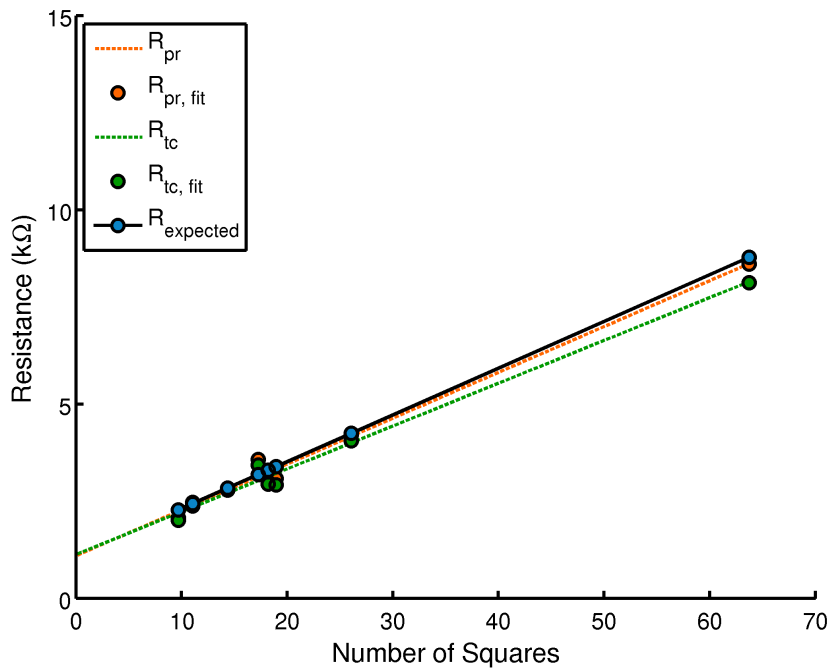
Alpha adjustment



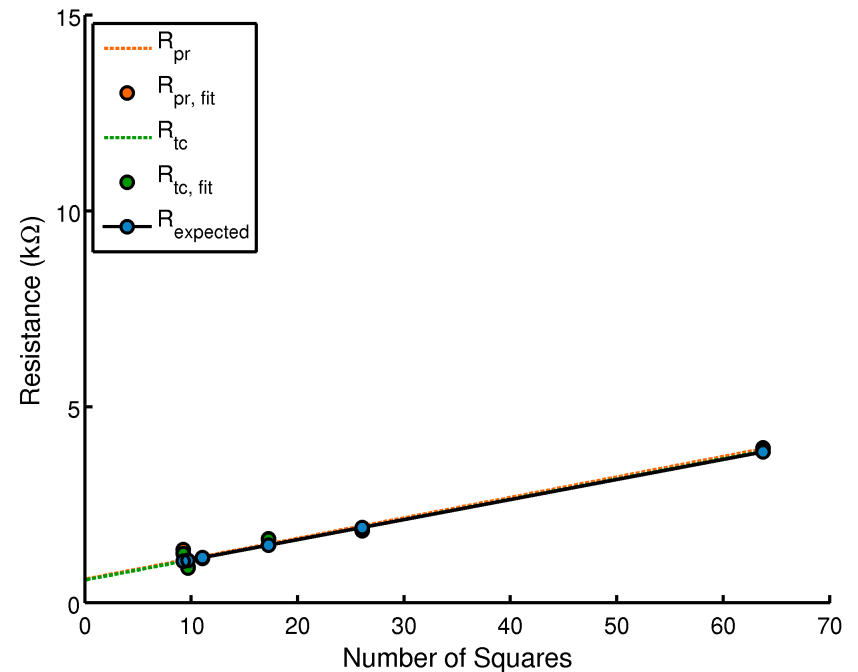
Overall impact?

- Noise $\sim 10x$ higher
 - Johnson noise - 2.5x increase
 - $1/f$ noise – 4x increase
- Sensitivity $\sim 4x$ higher
 - Beta^* - 2x larger
 - Thickness – 33% less
- Minimum detectable force increased by 2.5x, good enough for most applications

Resistance Analysis of PR Devices



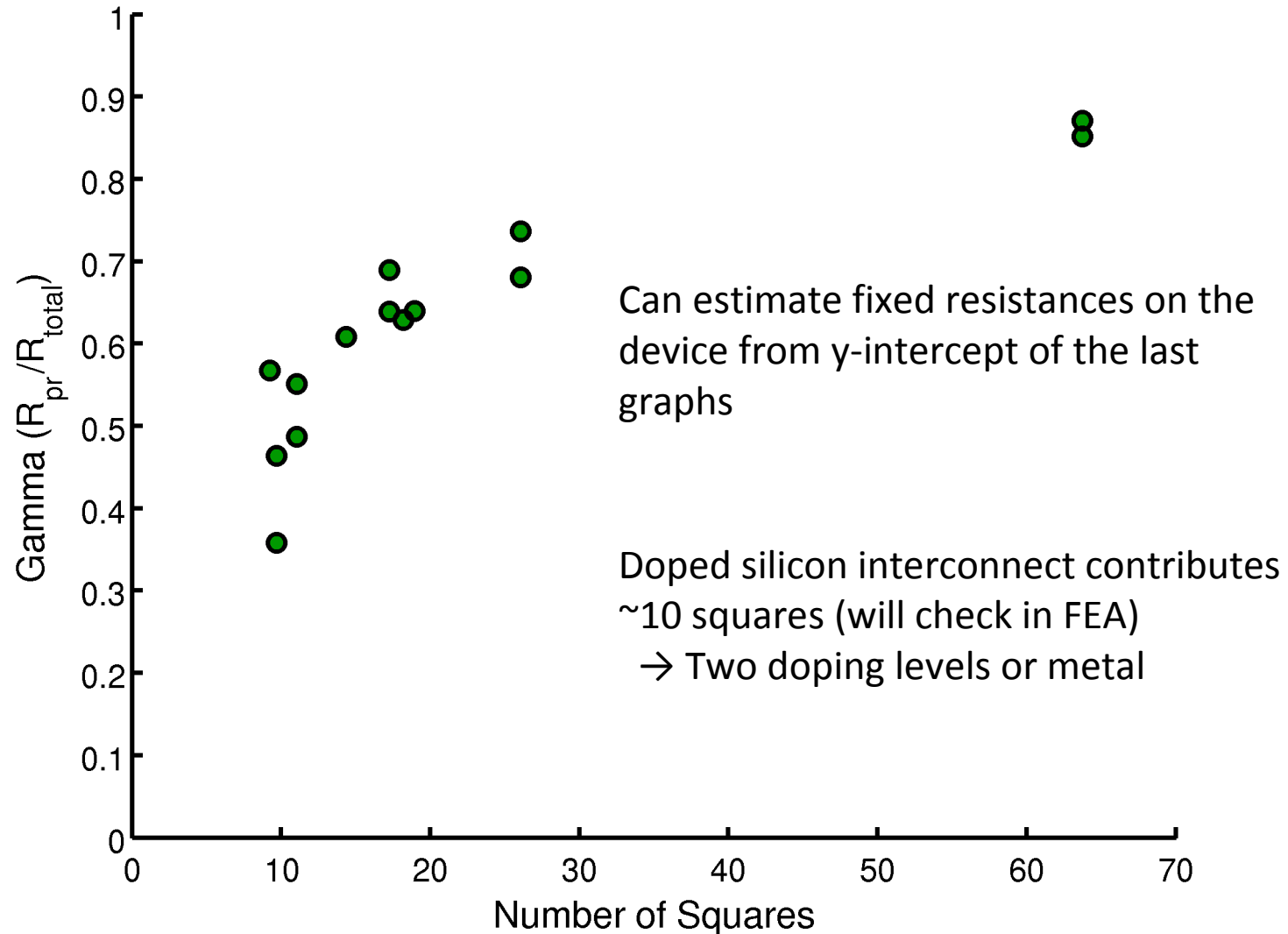
800C, 35 minutes



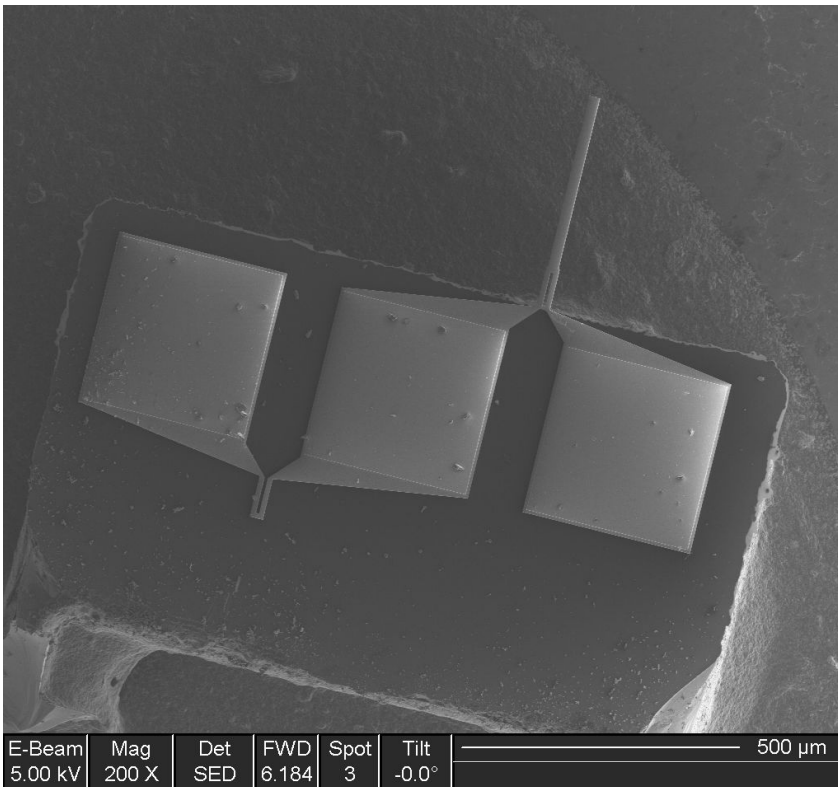
850C, 15 minutes

Assumed 100 nm undercut from litho/etch to improve fit (will measure)

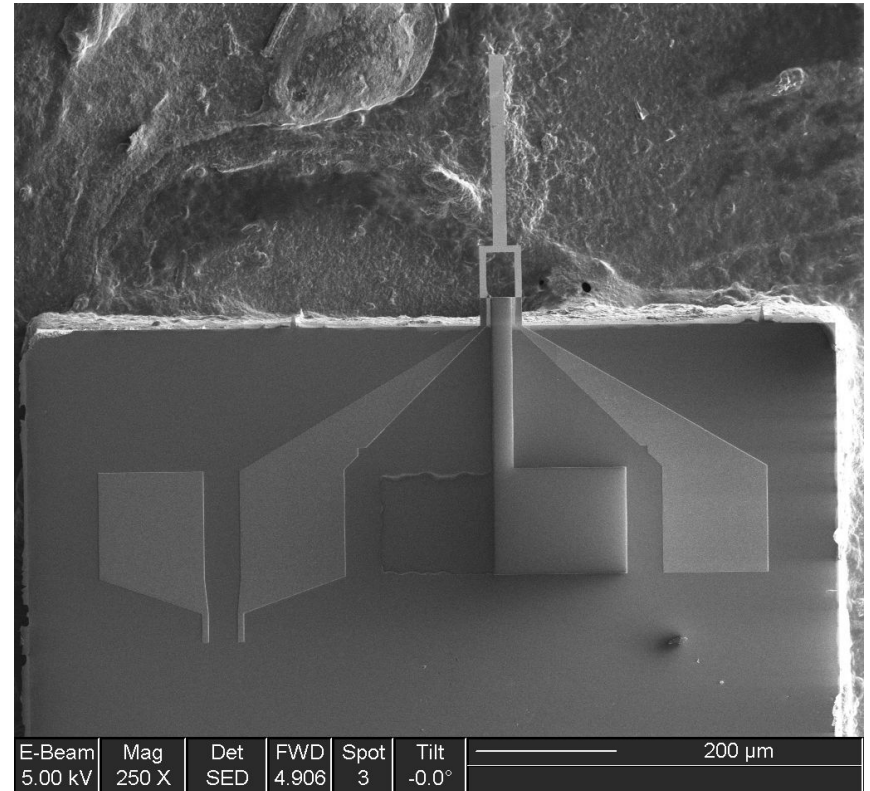
Resistance Analysis of PR Devices



PR interconnects



Doped Si interconnects

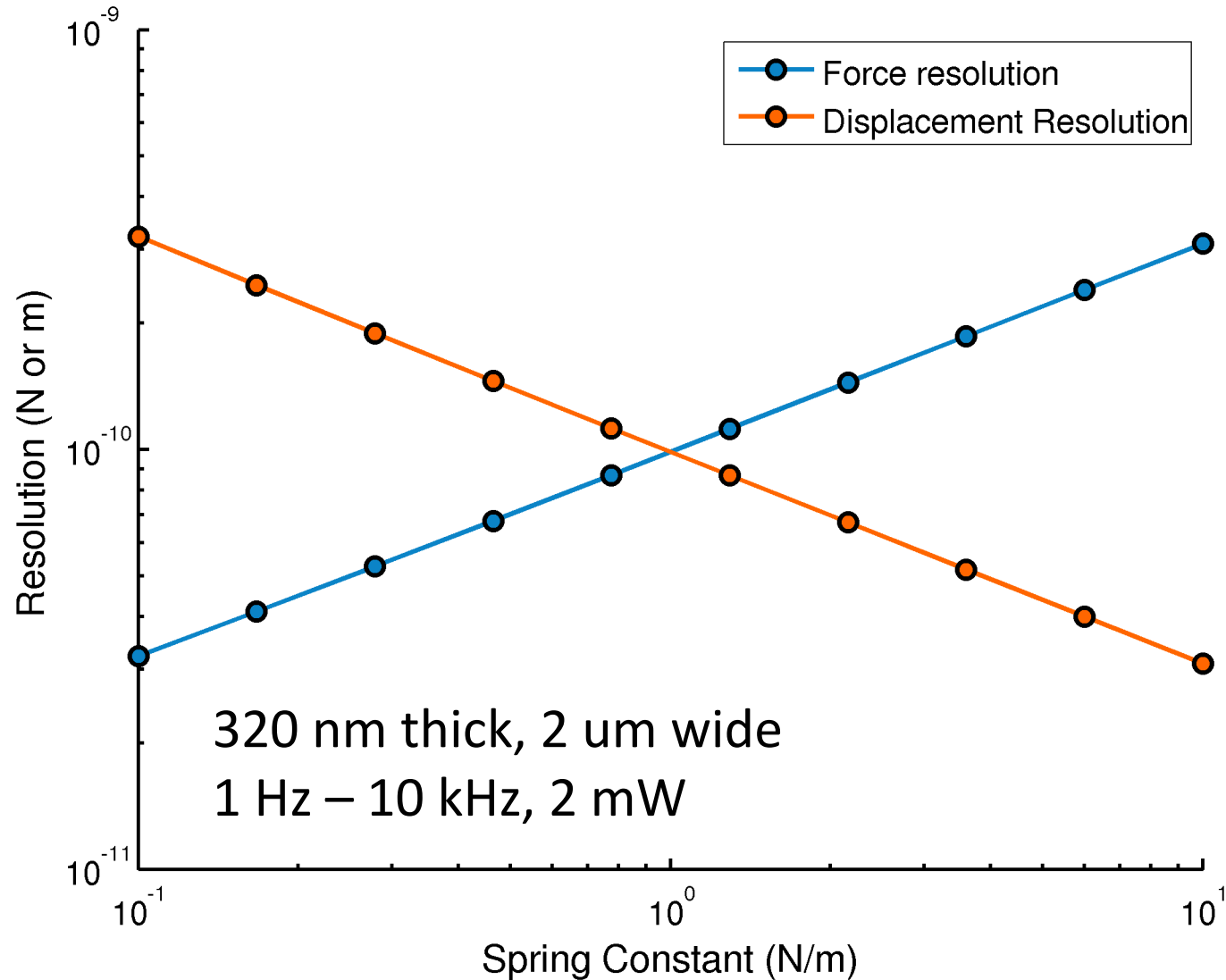


Al interconnects
w/ 10-30 μm square via

Sensitivity

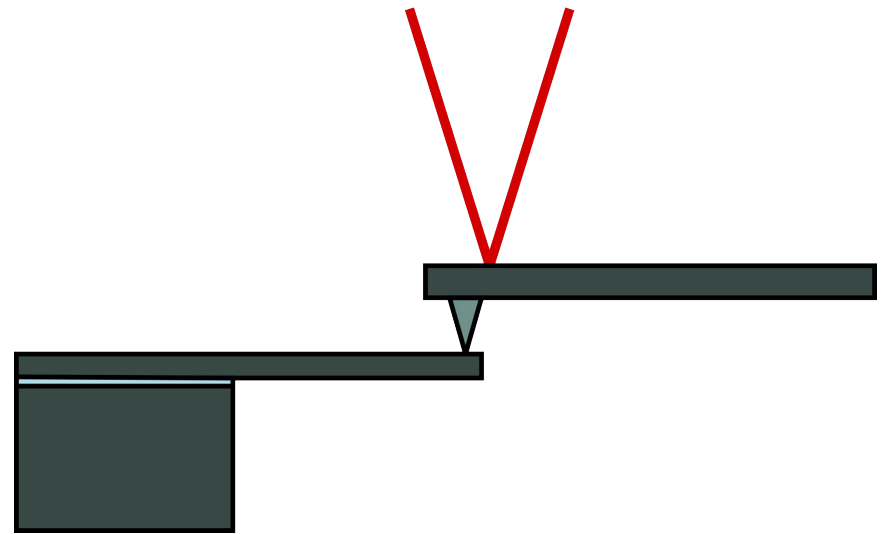
- Have had measurement issues
- Fixed PR output independent of wheatstone bridge bias voltage
- Devices optimized for high force sensitivity, low displacement sensitivity (i.e. long, soft levers)
- Piezoelectric shaker voltage couples to piezoresistor input (microvolts/nm)
- If displacement sensitivity isn't high enough, the PR signal is overwhelmed by the cross-talk signal

Force vs. Displacement Tradeoff



New Experiment Plan

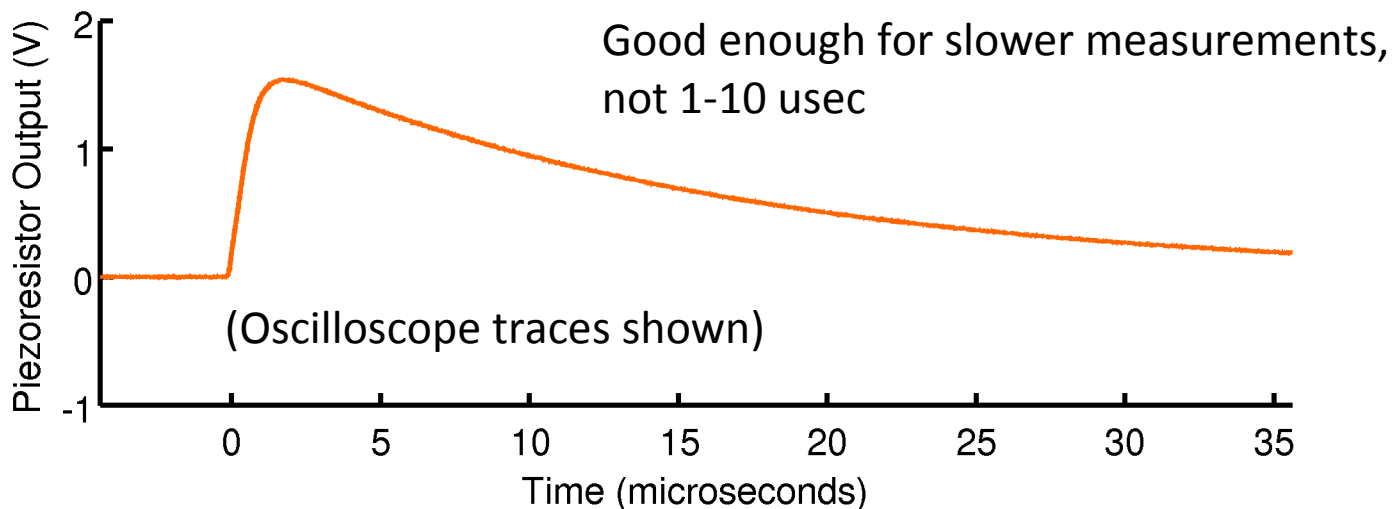
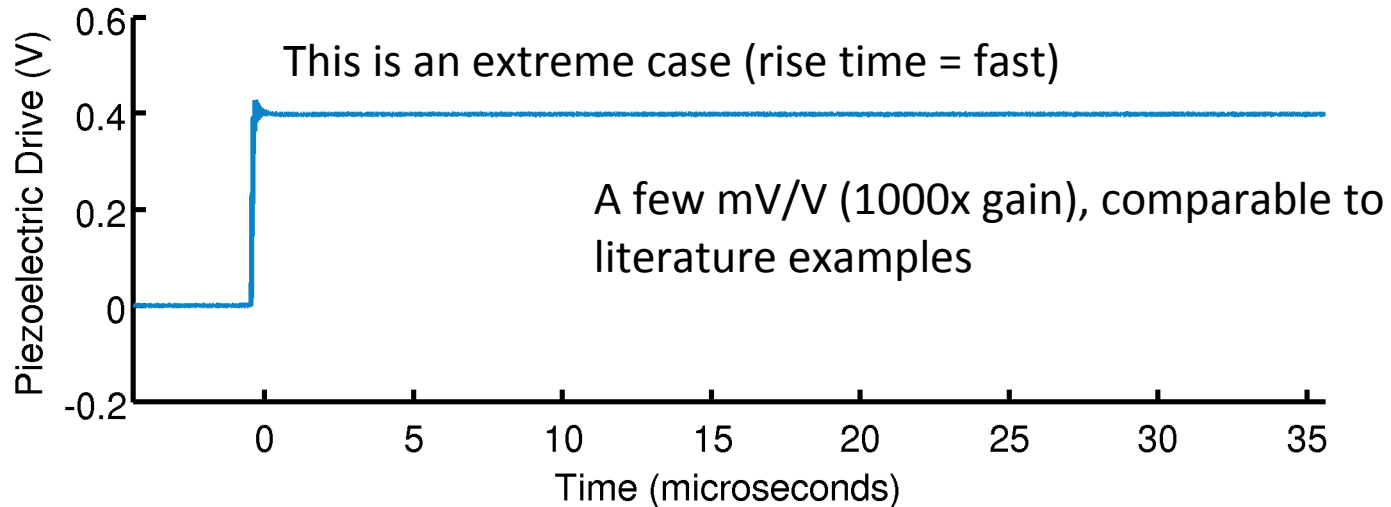
- AFM solves cross-talk problem
- But can't bounce the laser off of my devices
- Solution: mount the PR cantilever as a sample
- Can use for sensitivity, feedback



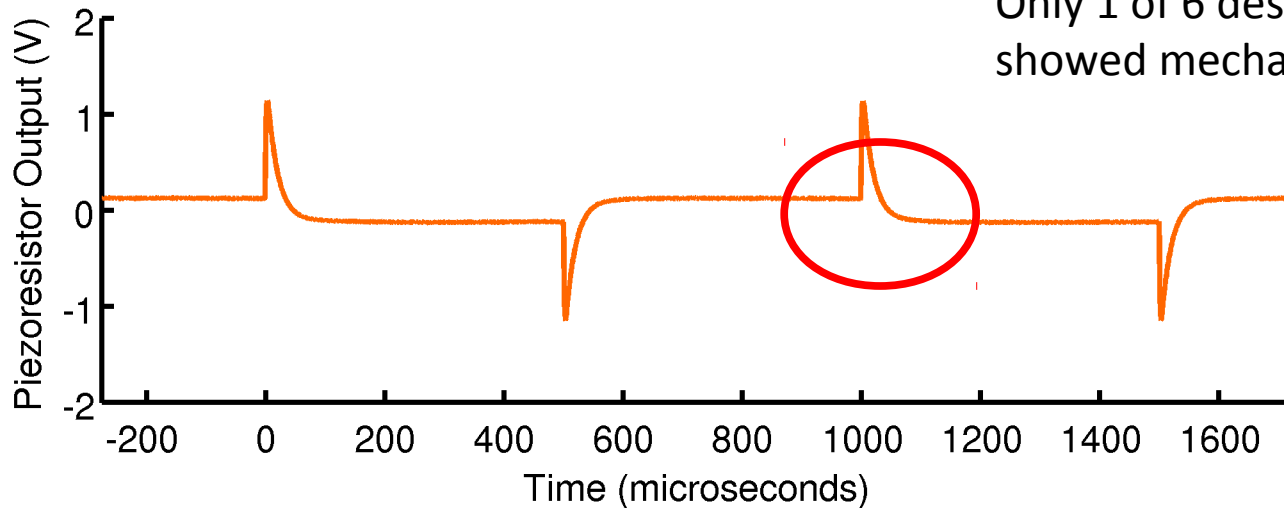
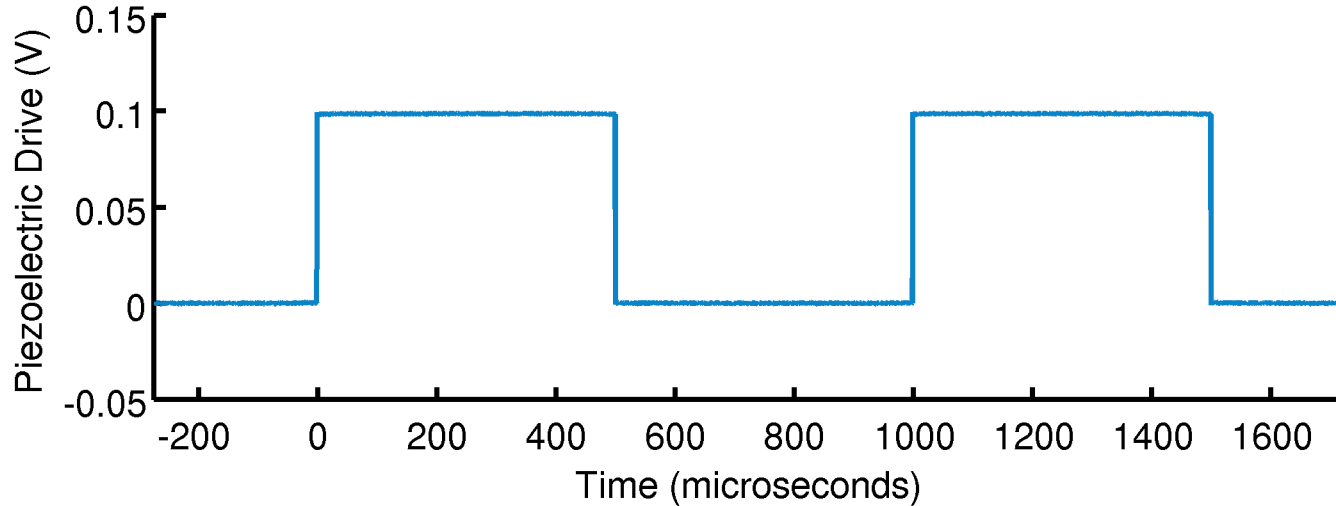
PE, PR Crosstalk

- Sensitivity and noise are great, but crosstalk could be the limiting factor
- Possible mechanisms
 - Capacitive: worse at higher frequencies, due to changing voltages in vicinity of each other
 - Mechanical: Piezoelectric bending changes piezoresistor resistance

There is capacitive crosstalk

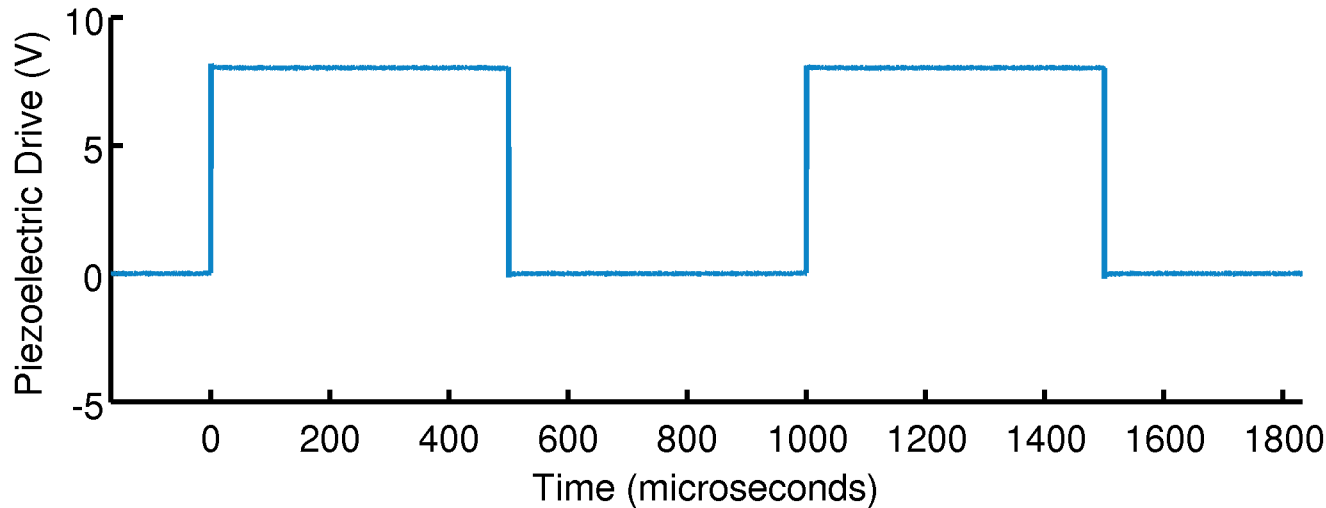


Some mechanical crosstalk

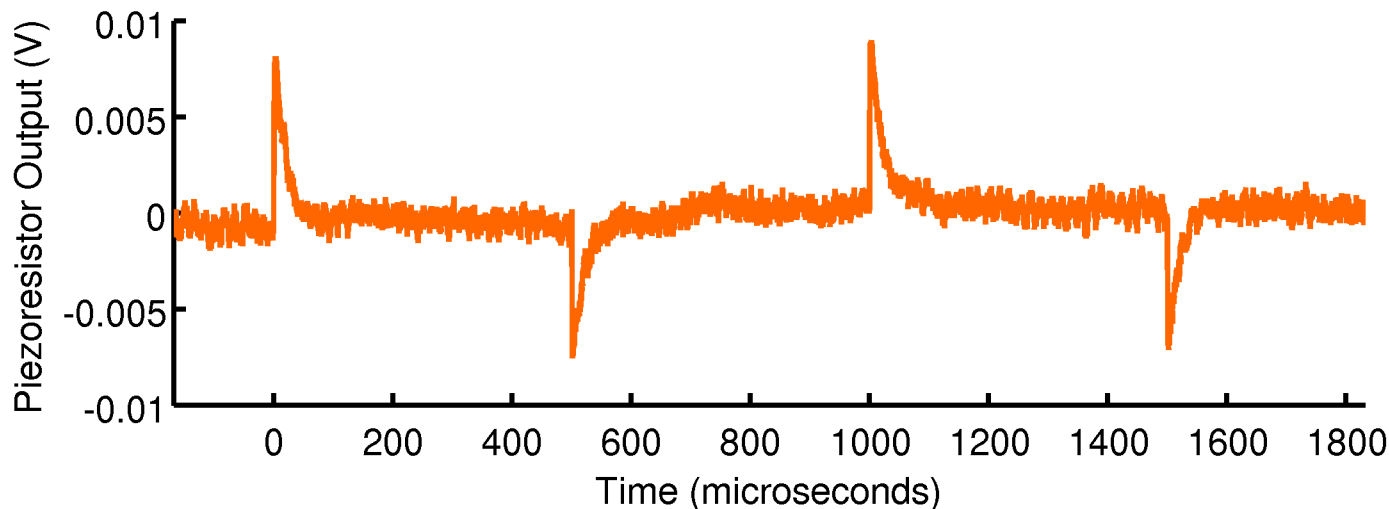


Only 1 of 6 designs tested
showed mechanical crosstalk

Minimal crosstalk from PCB

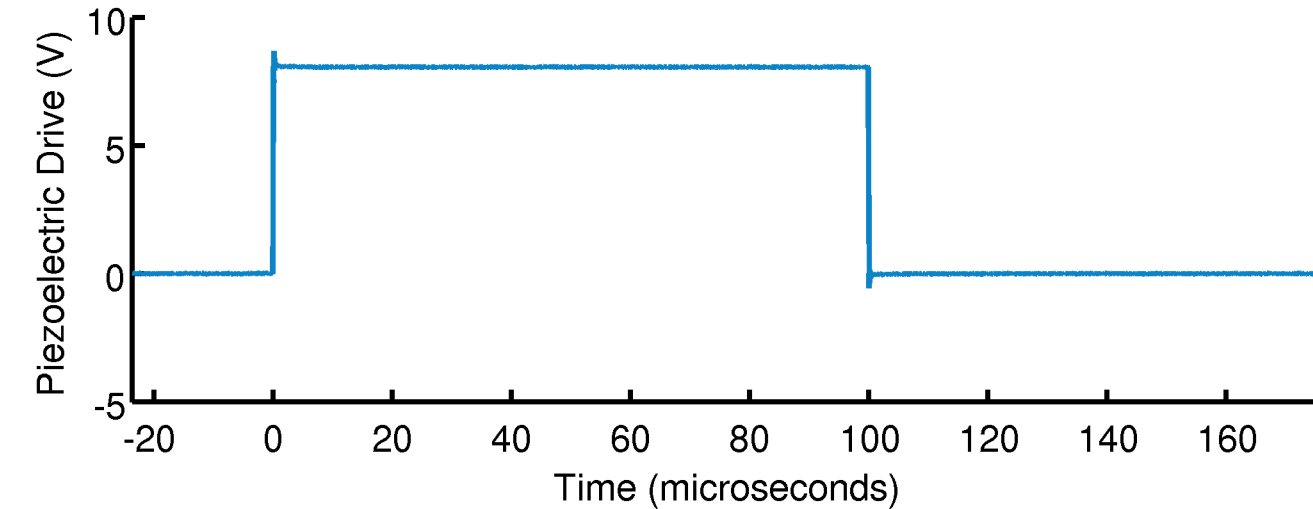


Connected discrete resistors and capacitors in place of the cantilever

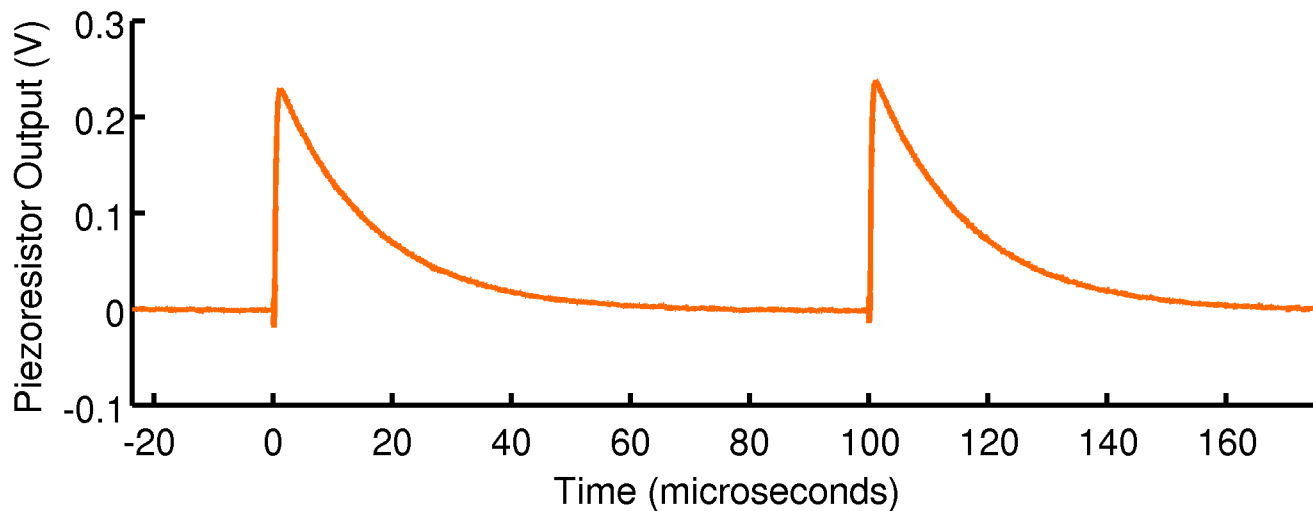


Also no crosstalk from the cable (shielded)

Some crosstalk from cantilever PCB



Connected cantilever
PCB, shorted the
bondpads by
wirebonding

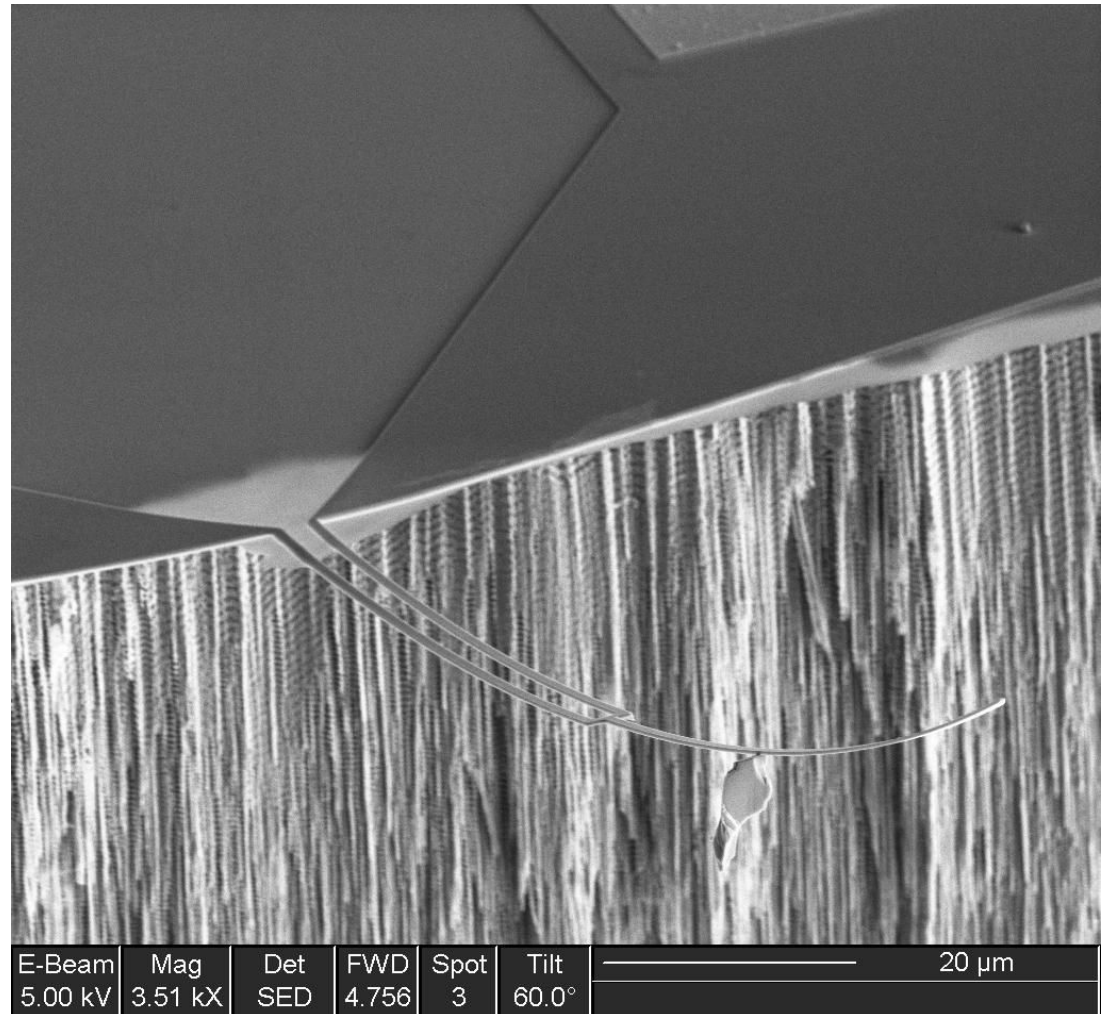


Crosstalk – What next?

- Modeling required
- Affects highest speed measurements, not bad enough to stop system development
- Slower measurements (msec) fine
- Possible solution: compensation on silicon die by placing piezoelectric next to temperature compensation PR

Bending Stress

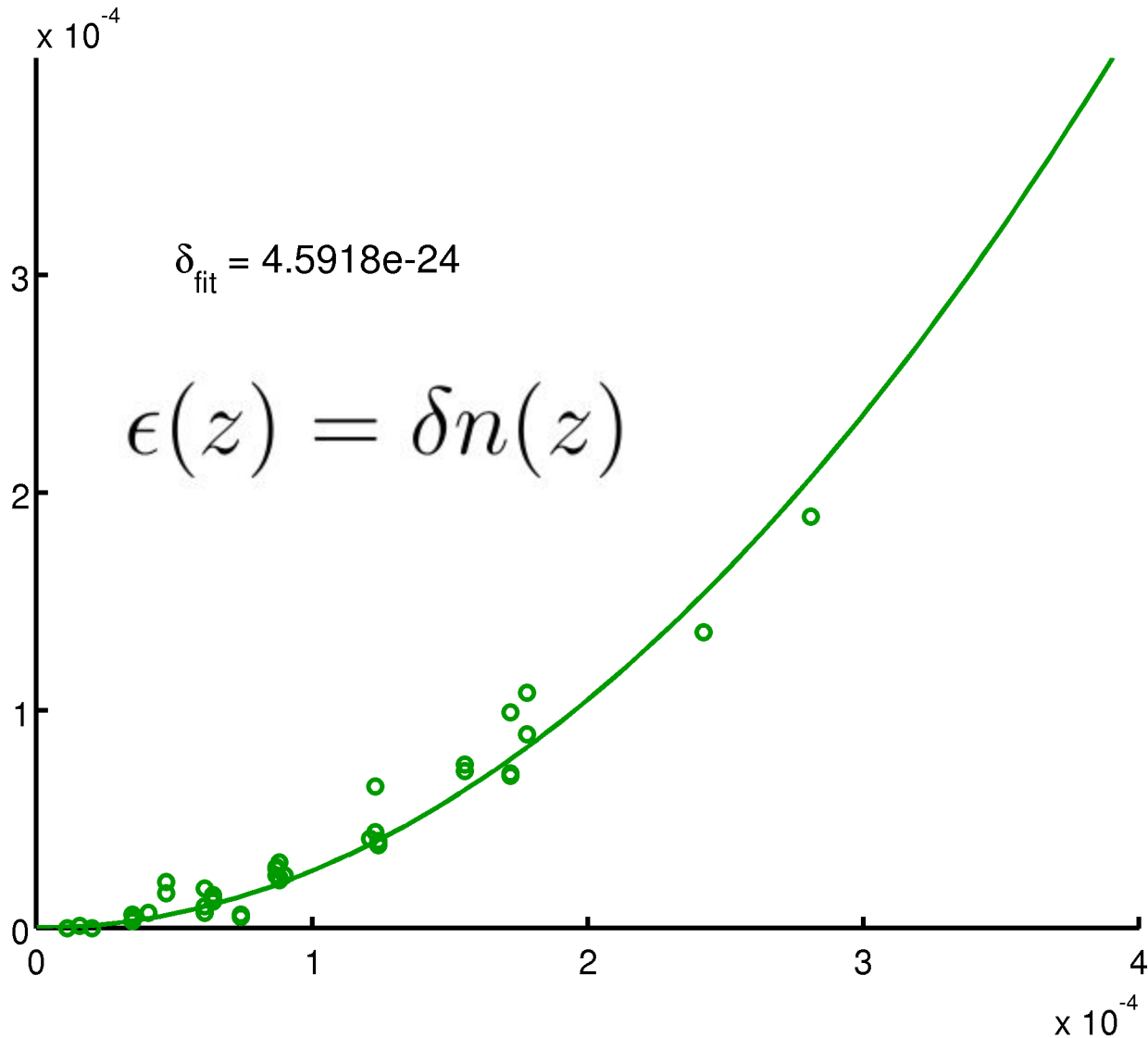
Why?



How Big is an Atom?

Group (vertical)		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
Period (horizontal)																			
		Atomic radii (pm)																	
1		H 25																	He
2		Li 145	Be 105											B 85	C 70	N 65	O 60	F 50	Ne
3		Na 180	Mg 150											Al 125	Si 110	P 100	S 100	Cl 100	Ar
4		K 220	Ca 180	Sc 160	Ti 140	V 135	Cr 140	Mn 140	Fe 140	Co 135	Ni 135	Cu 135	Zn 135	Ga 130	Ge 125	As 115	Se 115	Br 115	Kr
5		Rb 235	Sr 200	Y 180	Zr 155	Nb 145	Mo 145	Tc 135	Ru 130	Rh 135	Pd 140	Ag 160	Cd 155	In 155	Sn 145	Sb 145	Te 140	I 140	Xe
6		Cs 260	Ba 215	*	Hf 155	Ta 145	W 135	Re 135	Os 130	Ir 135	Pt 135	Au 135	Hg 150	Tl 190	Pb 180	Bi 160	Po 190	At	Rn
7		Fr	Ra 215	**	Rf	Db	Sg	Bh	Hs	Mt	Ds	Rg	Uub	Uut	Uuq	Uup	Uuh	Uus	Uuo
Lanthanides		*	La 195	Ce 185	Pr 185	Nd 185	Pm 185	Sm 185	Eu 185	Gd 180	Tb 175	Dy 175	Ho 175	Er 175	Tm 175	Yb 175	Lu 175		
Actinides		**	Ac 195	Th 180	Pa 180	U 175	Np 175	Pu 175	Am 175	Cm	Bk	Cf	Es	Fm	Md	Lr			

Cantilever Tip Deflection

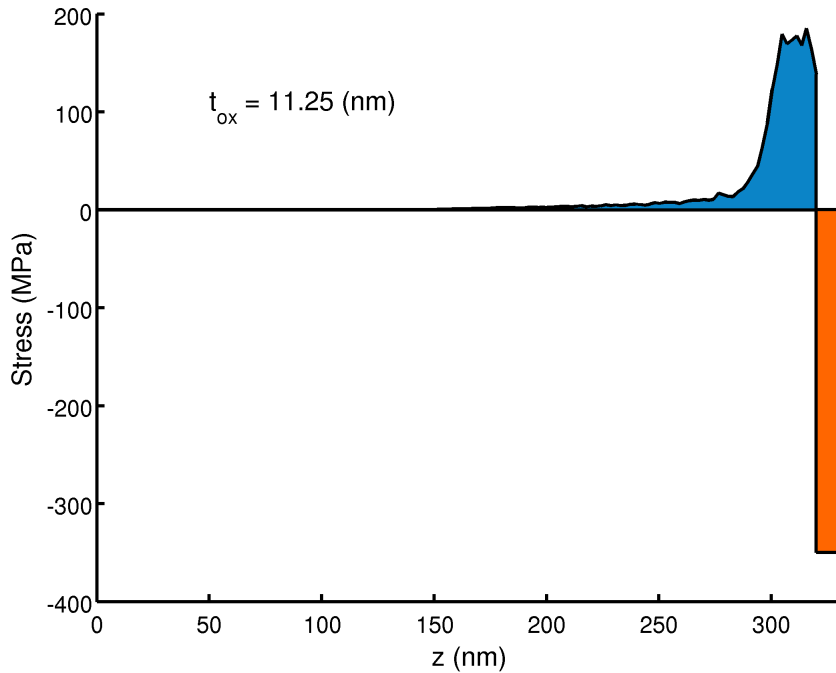


Compensation Strategy

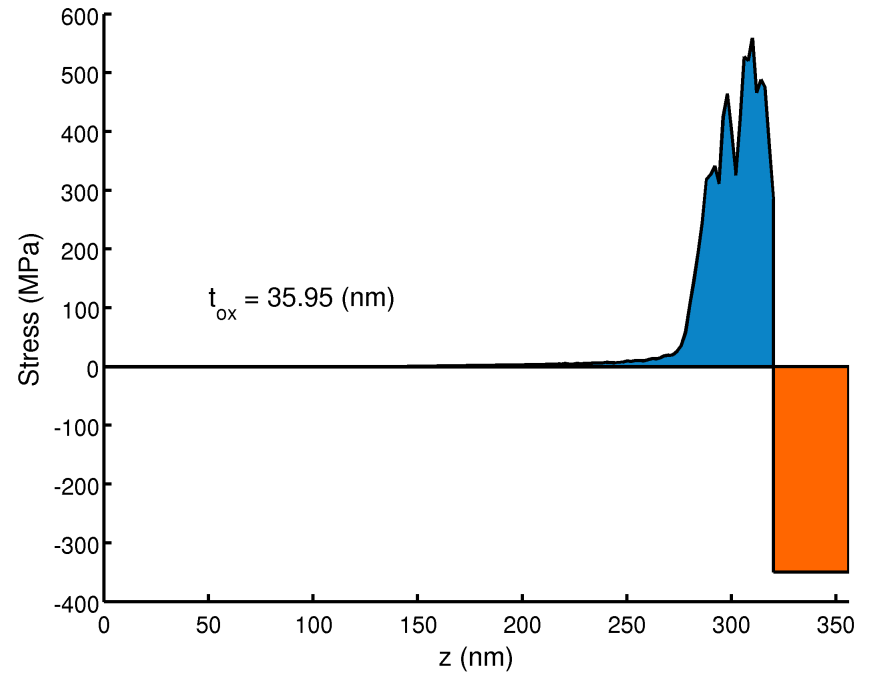
- Solution for tensile stress at the top surface
 - Tensile at the bottom
 - Compressive at the top
- SiO₂ is ideal
 - $E = 80 \text{ GPa}$
 - Stress = 350 MPa
- But how?
 - Thermal: Consumes Si, thermal budget (more diffusion)
 - LTO: Poor uniformity, time to deposit thin layers
 - PSG: Thickness control, unknown parameters
- How much oxide thickness?

Compensation Oxide

800C, 35 minutes



850C, 15 minutes

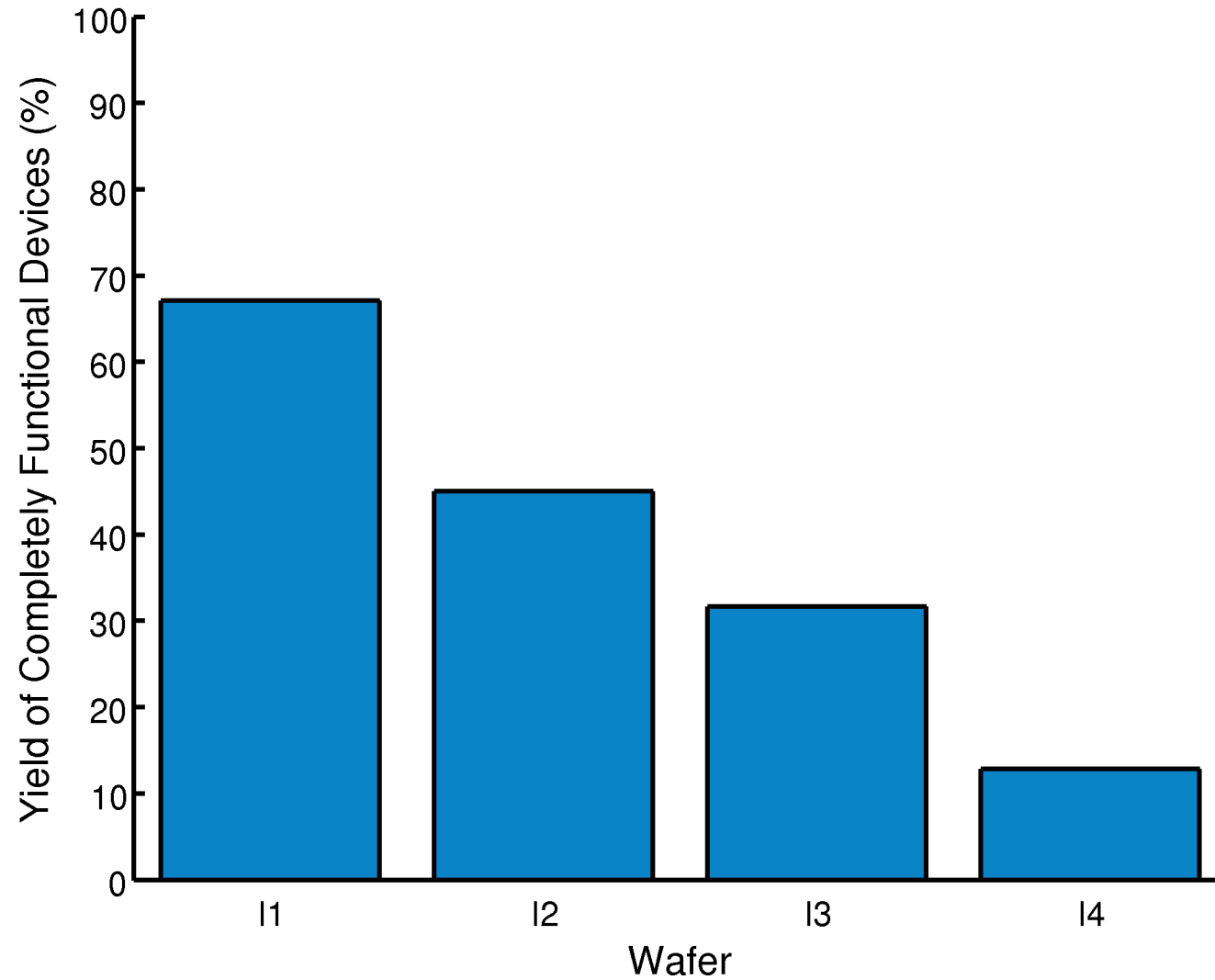


$$\sum M = \sum_i \int (z - \bar{z}) \sigma_i dA$$

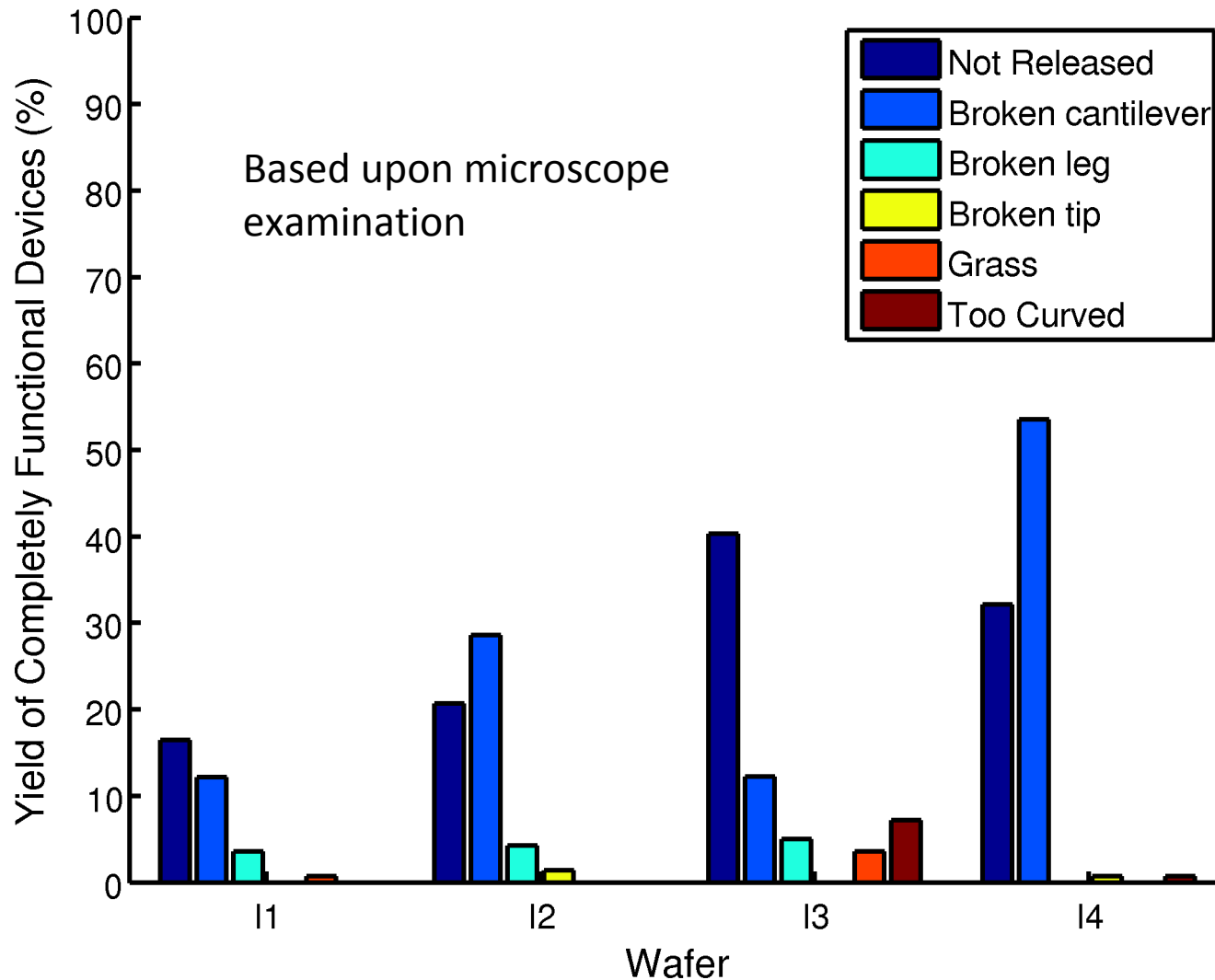
$$t_{oxide}^2 \left(\frac{\sigma_{oxide}}{2} \right) + t_{oxide} \left(\frac{t_{si} \sigma_{oxide}}{2} \right) + \int_0^{t_{si}} (z - \frac{t_{si}}{2}) \sigma_{si}(z) dz = 0,$$

$$0 = w_{si} \int_0^{t_{si}} (z - \bar{z}) \sigma_{si}(z) dz + w_{oxide} \int_{t_{si}}^{t_{si}+t_{oxide}} (z - \bar{z}) \sigma_{oxide} dz$$

Postmortem on PR Fab

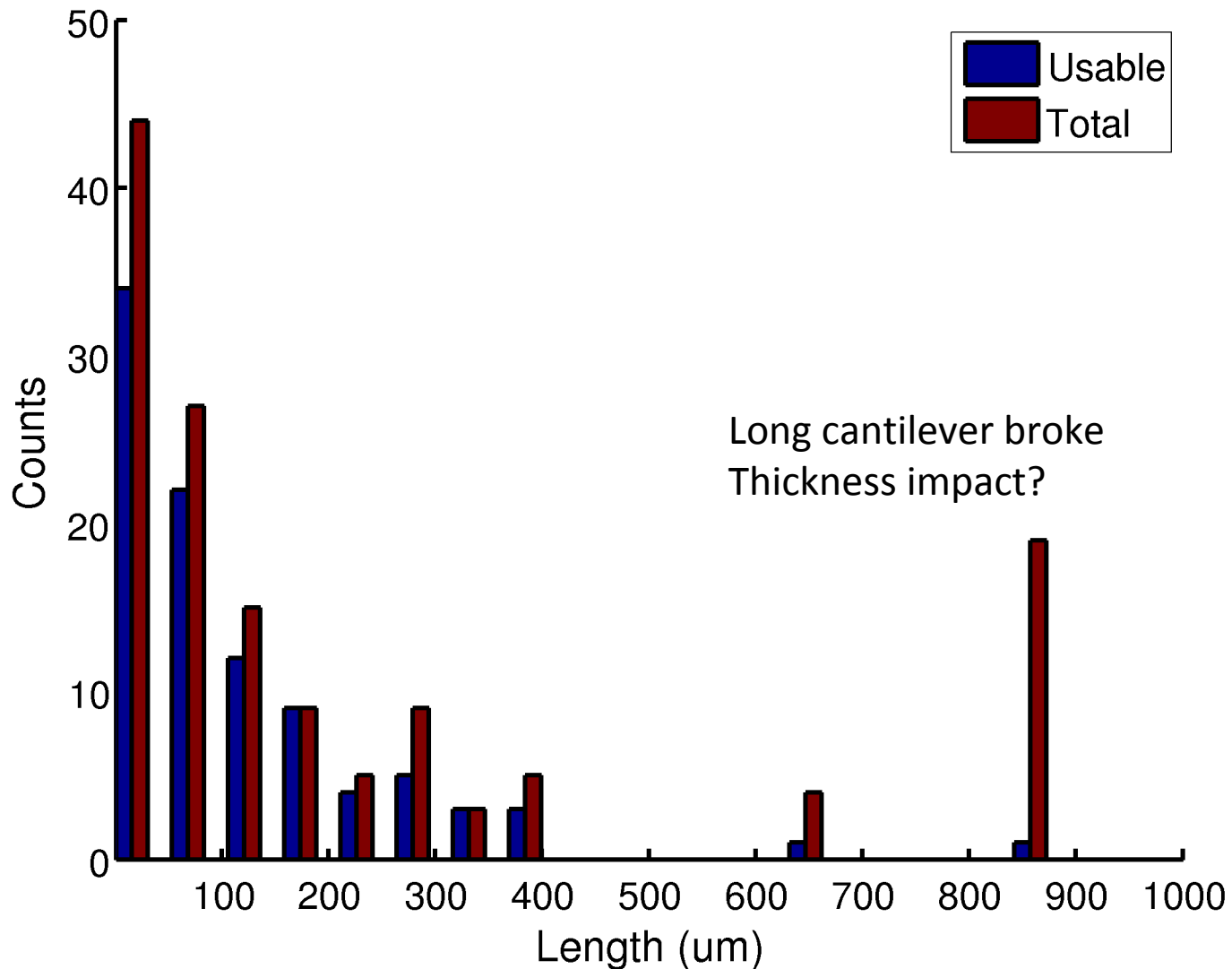


Failure types

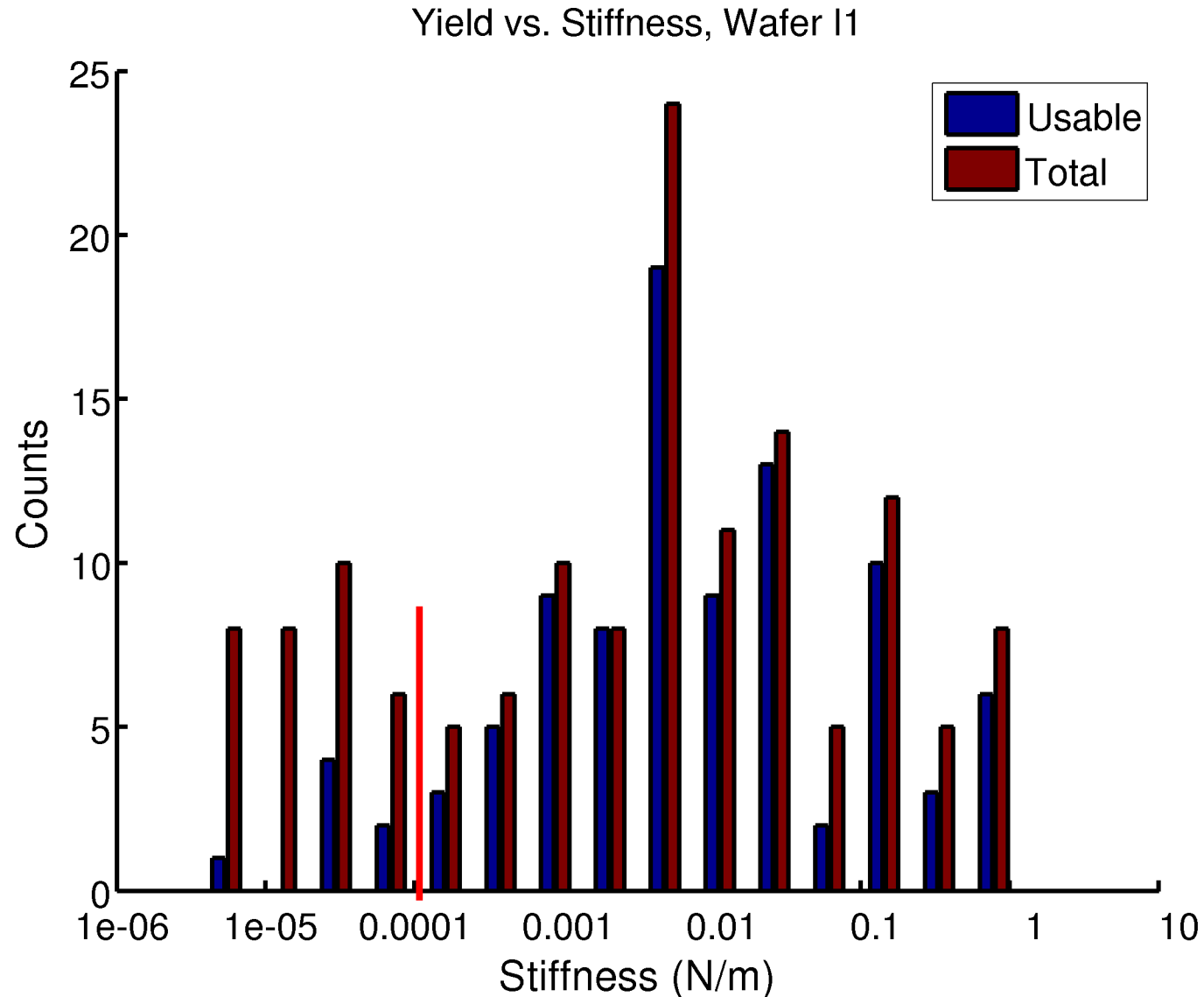


Which designs broke?

Yield vs. Length, Wafer I1



Which designs broke?



Conclusions

- Piezoresistors are noisier, higher resistance than expected, but minimal impact on performance
- There is electrical crosstalk on the microsecond scale
- Devices usable for system testing and some measurements
- Usual sensitivity calibration method doesn't work for (some) devices, will start doing some characterization on the AFM

What's Next?

- Sensitivity, feedback testing on AFM
- System prep for bio experiments
- Fab 2.0

